# MUX-16/MUX-28

16-CHANNEL/DUAL 8-CHANNEL

JFET ANALOG MULTIPLEXERS (OVERVOLTAGE PROTECTED)

Precision Monolithics Inc.

#### **FEATURES**

- JFET Switches Rather Than CMOS
- Highly Resistant To Static Discharge Damage
- No SCR Latch-up Problems
- Low "ON" Resistance 290ΩTypical
- Low Leakage Current
- Digital Inputs Compatible With TTL and CMOS
- Break-Before-Make Action
- 125° C Temperature-Tested Dice Available
- Overvoltage Protected
- Supply Loss Protection
- MUX-16 Pin Compatible With DG506, HI-506A, AD7506
- MUX-28 Pin Compatible With DG507, HI-507A, AD7507
- Available in Die Form

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# ORDERING INFORMATION †

-		PACKAGE						
25°C RESISTANCE	CERDIP 28-PIN	LCC 28-CONTACT	PLASTIC 28-PIN	TEMPERATURE RANGE				
290Ω	MUX16AT*		_	MIL				
290Ω	MUX16ET	-		IND				
$400\Omega$	MUX16BT*	MUX16BTC/883		MIL				
400Ω	MUX16FT	_	MUX16FP	XIND				
400Ω	-		MUX16FPC	XIND				
290Ω	MUX28AT*	-	_	MIL				
290Ω	MUX28ET	<b>_</b>	_	IND				
400Ω	MUX28BT*	MUX28BTC/883	<u> </u>	MIL				
400Ω	MUX28FT	-	MUX28FP	XIND				
400Ω		_	MUX28FPC	XIND				

<sup>\*</sup> For devices processed in total compliance to MIL-STD-883, add /883 after part number. Consult factory for 883 data sheet.

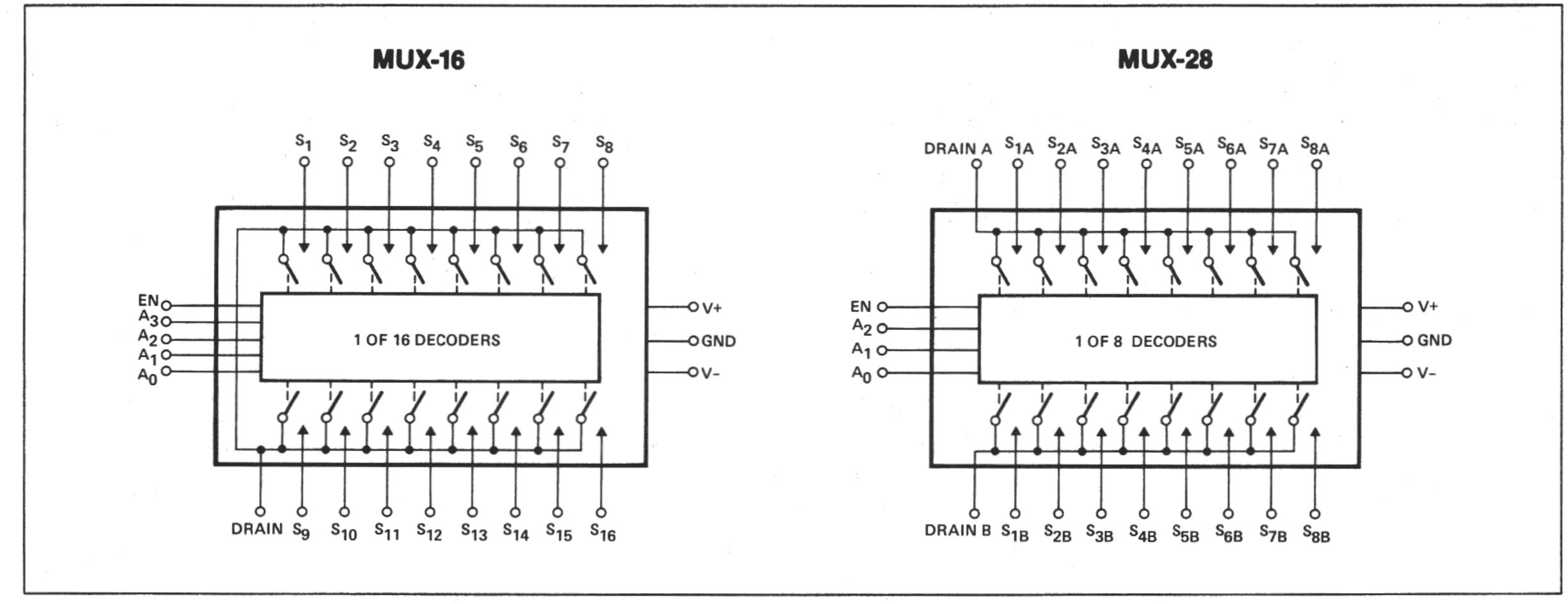
#### **GENERAL DESCRIPTION**

The MUX-16 is a monolithic 16-channel analog multiplexer which connects a single output to 1 of the 16 analog inputs depending upon the state of a 4-bit binary address. Disconnection of the output is provided by a logical "0" at the ENABLE input, thereby providing a package selection function.

The MUX-28 is a monolithic 8-channel differential analog multiplexer configured in a double pole, 8-position (plus OFF) electronic switch array. A 3-bit binary input address connects a pair of independent analog inputs from each 8-channel input section to the corresponding pair of independent analog outputs. Disconnection of both inputs is provided by a logical "0" at the ENABLE input, thereby offering a package select function.

Fabricated with Precision Monolithics' high performance Bipolar-JFET technology, these devices offer low, constant "ON" resistance. Performance advantages include low leakage currents and fast settling time with low crosstalk to satisfy a wide variety of applications. These multiplexers do not suffer from latch-up or static discharge blow-out problems associated with similar CMOS parts. The digital inputs are designed to operate from both TTL and CMOS levels while always providing a definite break-before-make action without the need for external pull-up resistors. For single 8-channel and dual 4-channel models, refer to the MUX-08/MUX-24 data sheet.

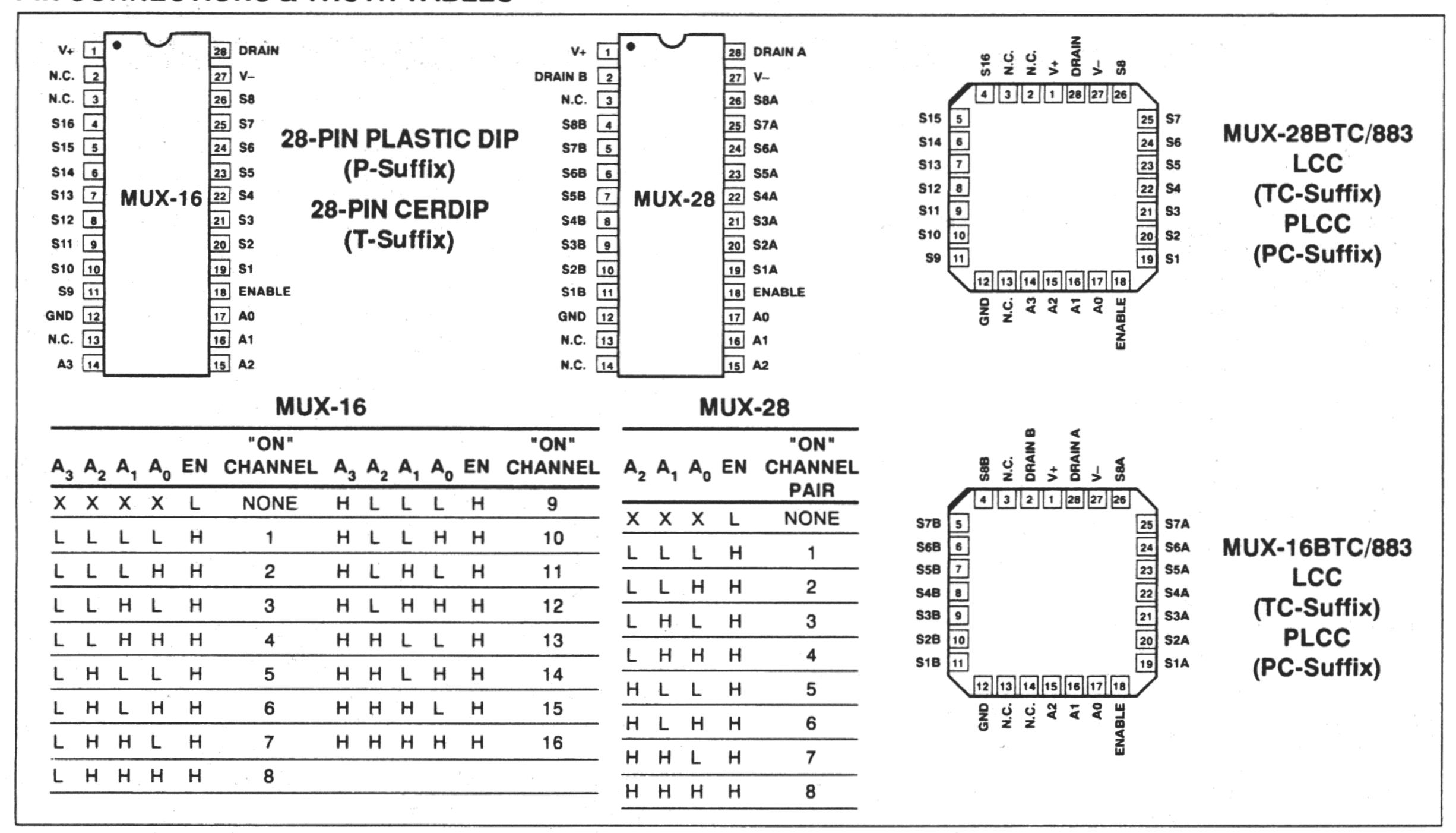
#### **FUNCTIONAL DIAGRAMS**



<sup>†</sup> Burn-in is available on commercial and industrial temperature range parts in CerDIP, plastic DIP, and TO-can packages. For ordering information, see 1990/91 Data Book, Section 2.



### **PIN CONNECTIONS & TRUTH TABLES**



# ABSOLUTE MAXIMUM RATINGS (Note 1) www.datasheetcatalog.com

Operating Temperature Range,	
MUX-16/28-AT, BT, BTC	55°C to +125°C
MUX-16/28-ET	25°C to +85°C
MUX-16/28-FP, FPC, FT	40°C to +85°C
Junction Temperature (T <sub>j</sub> )	65°C to +150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (Soldering, 60 sec)	300°C
Maximum Junction Temperature	150°C
V+ Supply to V- Supply	36V
Logic Input Voltage (V- or	
Analog Input Voltage V- Supply -20V t	

Maximum Current Throu	igh Any Pin	•	25mA
PACKAGE TYPE	⊖ <sub>jA</sub> (Note 2)	e <sub>jc</sub>	UNITS
28-Pin Hermetic DIP (T)	55	15	°C/W
28-Pin Plastic DIP (P)	56	30	°C/W
28-Contact LCC (TC)	86	35	°C/W
28-Contact PLCC (PC)	70	33	°C/W
NOTES.			

#### NOTES:

- 1. Ratings apply to both DICE and packaged parts, unless otherwise noted.
- 2. Θ<sub>jA</sub> is specified for worst case mounting conditions, i.e., Θ<sub>jA</sub> is specified for device in socket for CerDIP, P-DIP, and LCC packages; Θ<sub>jA</sub> is specified for device soldered to printed circuit board for PLCC package.

# **ELECTRICAL CHARACTERISTICS** at $V_S = \pm 15V$ and $T_A = 25^{\circ}$ C, unless otherwise noted.

					JX-16/ JX-28/			B/F B/F		
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
"ON" Resistance	R <sub>ON</sub>	$V_S \le 10V$ , $I_S \le 200 \mu A$			290	380		400	580	Ω
ΔR <sub>ON</sub> With Applied Voltage	$\Delta R_{ON}$	$-10V \le V_S \le 10V$ , $I_S = 200 \mu A$	*	_	1.5	5	<u> </u>	1.5	5	%
R <sub>ON</sub> Match Between Switches	R <sub>ON</sub> Match	$V_S = 0V$ , $I_S = 200 \mu A$			7	15		9	20	%
Analog Voltage Range	V <sub>A</sub>	(Note 6)		+ 10 - 10	+ 11 -15		+10 -10	+11 -15		V
Source Current (Switch "OFF")	I <sub>S</sub> (OFF)	$V_S = 10V, V_D = -10V \text{ (Note 1)}$		-	0.01	1		0.01	2	nA
Drain Current (Switch "OFF")	I <sub>D</sub> (OFF)	$V_S = 10V, V_D = -10V \text{ (Note 1)}$	MUX-16 MUX-28		0.2	1		0.2 0.1	2	nA
Leakage Current (Switch "ON")	I <sub>D</sub> (ON) +I <sub>S</sub> (ON)	V <sub>D</sub> = 10V (Note 1)	MUX-16 MUX-28		0.2	1		0.2 0.1	2	nA
Digital Input Current	I <sub>IN</sub>	V <sub>IN</sub> = 0.4V to 15V	-	-	1	10		1.	10	μΑ



# **ELECTRICAL CHARACTERISTICS** at $V_S = \pm 15V$ and $T_A = +25$ °C, unless otherwise noted. Continued

					IUX-16A IUX-28A		N N				
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	U	NITS
Digital "0" Enable Current	I <sub>INL</sub> (EN)	V <sub>EN</sub> = 0.4V		-	4	10		4	10	,	μΑ
Digital Input Capacitance	C <sub>DIG</sub>	- ·		_	3	<del>-</del> .	· · · · · · · · · · · · · · · · · · ·	3			pF
Switching Time (t <sub>TRAN</sub> )	t <sub>PHL</sub>	(Notes 2,5) Figure 1 (Test Circuits)			1.4 1.2	2.0 1.8		1.8 1.6	2.5 2.2		μS
Output Settling Time	ts	10V Step to 0.10% 10V Step to 0.05% 10V Step to 0.02%		- -	2.6 3.2 4.0			2.7 3.4 7.2	- -		μS
Break-Before-Make Delay	tOPEN	Figure 3		_	0.7	_	<del>-</del>	1			μS
Enable Delay "ON"	t <sub>on (EN)</sub>	(Note 5) Figure 2 (Test Circuits)		_	1	2	_	1.2	2.5		μS
Enable Delay "OFF"	t <sub>OFF (EN)</sub>	(Note 5) Figure 2 (Test Circuits)	MUX-16 MUX-28		0.25 0.25	0.5 0.5	<del>-</del>	0.25 0.25	0.5 0.6		μS
"OFF" Isolation	ISO <sub>OFF</sub>	(Note 4) Figure 4 (Test Circuits)		_	66			66	_	4	dB
Crosstalk	СТ	(Note 3) Figure 5 (Test Circuits)		- -	75	-	· -	75	-		dB
Source Capacitance	C <sub>S (OFF)</sub>	Switch "OFF," $V_S = 0V, V_D = 0V$	,	_	2.5	_	-	2.5	_		pF
Drain Capacitance	C <sub>D (OFF)</sub>	Switch "OFF," $V_S = 0V, V_D = 0V$	MUX-16 MUX-28		13 8	_	: <u>-</u>	13 8	_		pF
Input to Output Capacitance	C <sub>DS (OFF)</sub>	(Note 4)		-	0.15	_		0.15	-		pF
Positive Supply Current (All Digital Inputs	1+	V+ = 15V	MUX-16 MUX-28		15 15	19 19		9	19		mA
Logic "0" or "1")		V+ = 5V	MUX-16 MUX-28	_	12 12	_	_	8 7	_	2 7 ° .	
Negative Supply Current (All Digital Inputs	<b> -</b>	V- = -15V	MUX-16 MUX-28	_	5 5	7		3.5	7		mA
Logic "0" or "1")	•	V-=-5V	MUX-16 MUX-28		4	_	_	3 2.5			

### NOTES:

- 1. Conditions applied to leakage tests insure worst case leakages.
- 2.  $R_L = 10M\Omega$ ,  $C_L = 10pF$ .
- 3. Crosstalk is measured by driving channel 8 (8B\*) with channel 7 (7B\*) ON.  $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_S = 5V$  RMS, f = 500kHz.
- 4. "OFF" isolation is measured by driving channel 8 (8B) with ALL channels OFF.  $R_L = 1k\Omega$ ,  $C_L = 10pF$ ,  $V_S = 5V$  RMS, f = 500kHz.  $C_{DS}$  is computed from the OFF isolation measurement.
- 5. Sample tested.
- 6. Guaranteed by leakage current and R<sub>ON</sub> tests.

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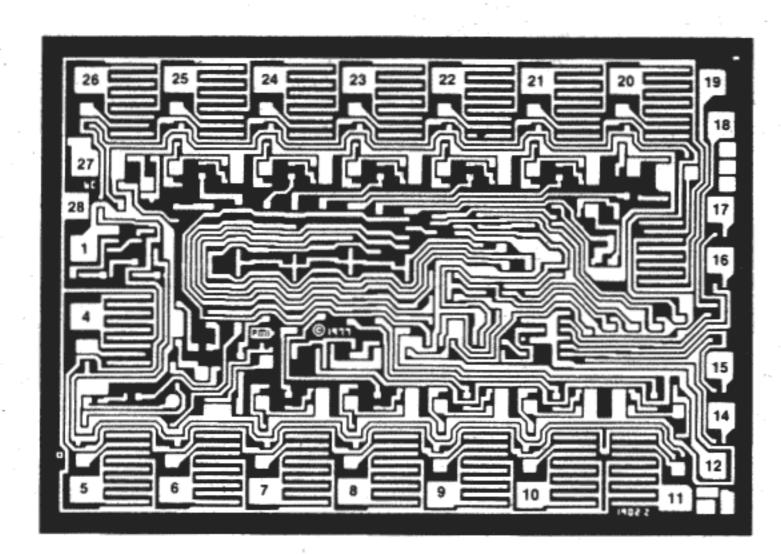
**ELECTRICAL CHARACTERISTICS** at  $V_S = \pm 15V$ ,  $-55^{\circ}C \le T_A \le +125^{\circ}C$  for MUX-16AT/BT/BTC and MUX-28AT/BT/BTC;  $-25^{\circ}C \le T_A \le +85^{\circ}C$  for MUX-16ET and MUX-28ET;  $-40^{\circ}C \le T_A \le +85^{\circ}C$  for MUX-16 FT/FP/FPC and MUX-28FT/FP/FPC, unless otherwise noted.

-				MUX-16A/E MUX-28A/E			MUX-16B/F MUX-28B/F		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
"ON" Resistance	RON	$V_{S} \le 10, I_{S} \le 200 \mu A$		_	500	_		800	Ω
ΔR <sub>ON</sub> With Applied Voltage	ΔR <sub>ON</sub>	$-10V \le V_S \le 10V$ , $I_S = 200 \mu A$	_	2	_	_	5.5	_	%
R <sub>ON</sub> Match Between Switches	R <sub>ON</sub> Match	$V_S = 0V, I_S = 200\mu A$	-	10		***	15	-	%
Analog Voltage Range	V <sub>A</sub>	(Note 6)	+10 -10	+11 -15		+10 -10	+11 -15		V
Source Current (Switch "OFF")	I <sub>S (OFF)</sub>	$V_S = 10V, V_D = -10V \text{ (Note 1)}$	-	_	25	_	-	50	nA
Drain Current (Switch "OFF")	I <sub>D (OFF)</sub>	$V_S = 10V, V_D = -10V \text{ (Note 1)}$			75	_		250	nA
Leakage Current (Switch "ON")	I <sub>D (ON)</sub> +I <sub>S (ON)</sub>	V <sub>D</sub> = 10V (Note 1)	:	· —	75		_	250	nA
Digital "1" Input Voltage	V <sub>INH</sub>	(Note 6)	2	_	_	2	_	_	V
Digital "0" Input Voltage	V <sub>INL</sub>	(Note 6)	<del>_</del>	_	0.7	_		0.7	V
Digital Input Current	I <sub>IN</sub>	V <sub>IN</sub> = 0.4V to 15V			20	—	_	20	μА
Digital "0" Enable Current	I <sub>INL</sub> (EN)	V <sub>EN</sub> = 0.4V	_	_	20	_		20	μА
Positive Supply Current	1+	All Digital Inputs Logic "0" or "1"	_	_	24	_	_	24	mA
Negative Supply Current	1-	All Digital Inputs Logic "0" or "1"	_		8.2	_	_	8.2	mA



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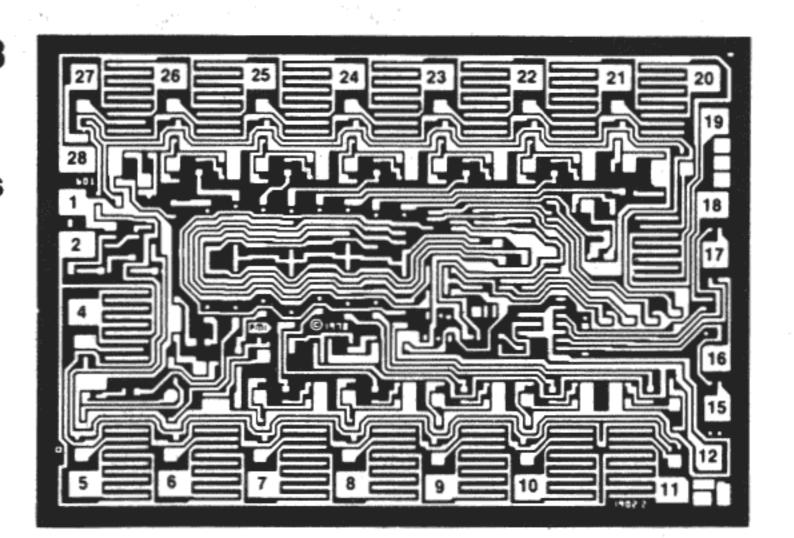
# DICE CHARACTERISTICS (125°C TESTED DICE AVAILABLE)



**MUX-16 MUX-28** 

DIE SIZE  $0.110 \times 0.076$  inch, 8360 sq. mils  $(2.794 \times 1.930 \text{ mm}, 5392 \text{ sq. mm})$ 

For additional DICE ordering information, refer to 1990/91 Data Book, Section 2.



1. POSITIVE SUPPLY 17. ADDRESS BIT 0 (A0) 4. SOURCE 16 (S16) 18. ENABLE 19. SOURCE 1 (S1) 5. SOURCE 15 (S15) 6. SOURCE 14 (S14) 20. SOURCE 2 (S2) 7. SOURCE 13 (S13) 21. SOURCE 3 (S3) 22. SOURCE 4 (S4) 8. SOURCE 12 (S12) 23. SOURCE 5 (S5) 9. SOURCE 11 (S11) 24. SOURCE 6 (S6) 10. SOURCE 10 (S10) 11. SOURCE 9 (S9) 25. SOURCE 7 (S7) 12. GROUND

26. SOURCE 8 (S8) 27. NEGATIVE SUPPLY (SUBSTRATE)

14. ADDRESS BIT 3 (A3) 15. ADDRESS BIT 2 (A2) 28. DRAIN

16. ADDRESS BIT 1 (A1)

1. POSITIVE SUPPLY 17. ADDRESS BIT 0 (A0) 18. ENABLE 2. DRAIN B 4. SOURCE 8 (S8B) 19. SOURCE 1 (S1A) 5. SOURCE 7 (S7B) 20. SOURCE 2 (S2A) 21. SOURCE 3 (S3A) 6. SOURCE 6 (S6B) 22. SOURCE 4 (S4A) 7. SOURCE 5 (S5B) 23. SOURCE 5 (S5A) 8. SOURCE 4 (S4B) 9. SOURCE 3 (S3B) 24. SOURCE 6 (S6A) 25. SOURCE 7 (S7A) 10. SOURCE 2 (S2B) 26. SOURCE 8 (S8A) 11. SOURCE 1 (S1B)

27. NEGATIVE SUPPLY (SUBSTRATE) 12. GROUND 15. ADDRESS BIT 2 (A2) 28. DRAIN A

16. ADDRESS BIT 1 (A1)

**WAFER TEST LIMITS** at V+=15V, V-=-15V,  $T_A=25^{\circ}$  C for MUX-16/28 N and G,  $T_A=125^{\circ}$  C for MUX-16/28 NT and GT, unless otherwise noted.

			MUX-16/ MUX-28NT	MUX-16/ MUX-28N	MUX-16/ MUX-28GT	MUX-16/ MUX-28G	
PARAMETER	SYMBOL	CONDITIONS	LIMIT	LIMIT	LIMIT	LIMIT	UNITS
"ON" Resistance	R <sub>ON</sub>	$V_S = 0V$ , $I_S = 200 \mu A$	540	380	800	580	Ω ΜΑΧ
Digital "1" Input Voltage	V <sub>INH</sub>		2	2	2	2	V MIN
Digital "0" Input Voltage	V <sub>INL</sub>		0.8	0.8	0.8	0.8	V MAX
Digital "0" Input Current	I <sub>INL</sub>	$V_{IN} = 0.4V$	20	10	20	10	μΑ ΜΑΧ
Digital "0" Enable Current	I <sub>INL(EN)</sub>	V <sub>EN</sub> = 0.4V	20	10	20	10	μΑ ΜΑΧ
Positive Supply Current (All Digital Inputs Logic "0")	1+		24	19	24	19	mA MAX
Negative Supply Current (All Digital Inputs Logic "0")	1-		8.2	7	8.2	7	mA MAX
Analog Input Range	V <sub>A</sub>	(Note 2)	±10	±10	±10	±10	VMIN

#### NOTE:

Electrical tests are performed at wafer probe to the limits shown. Due to variations in assembly methods and normal yield loss, yield after packaging is not guaranteed for standard product dice. Consult factory to negotiate specifications based on dice lot qualification through sample lot assembly and testing.

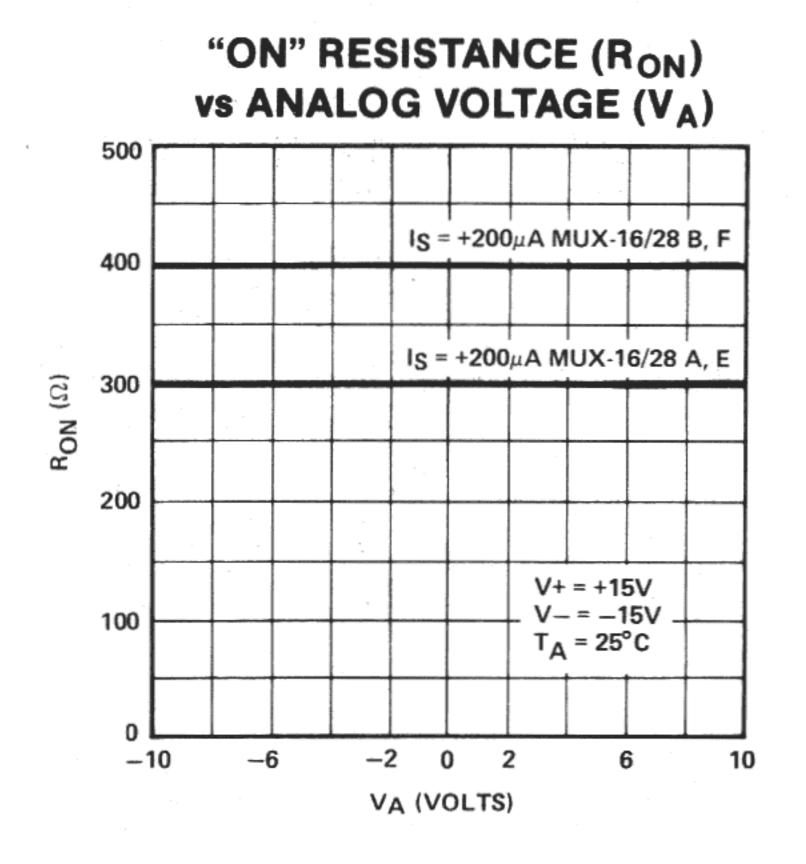
# **TYPICAL ELECTRICAL CHARACTERISTICS** at V+=15V, V-=-15V and $T_A=25^{\circ}$ C for MUX-16/28 N and G, $T_A=125^{\circ}$ C for MUX-16/28 NT and GT, unless otherwise noted.

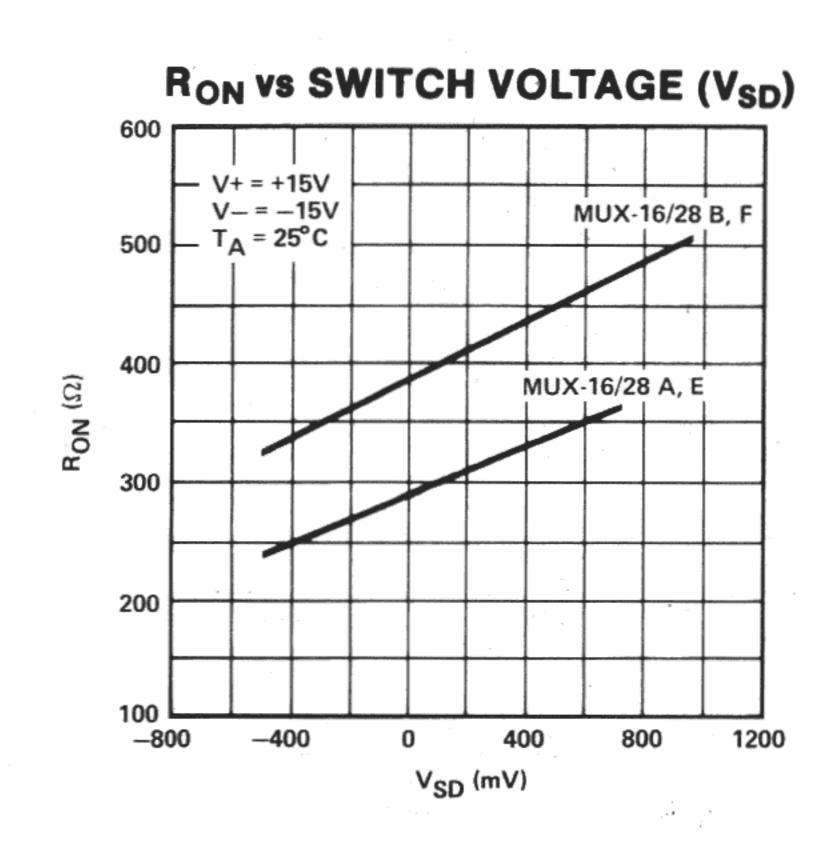
			MUX-16/ MUX-28NT	MUX-16/ MUX-28N	MUX-16/ MUX-28GT	MUX-16/ MUX-28G	
PARAMETER	SYMBOL	CONDITIONS	TYPICAL	TYPICAL	TYPICAL	TYPICAL	UNITS
Switching Time (t <sub>TRAN</sub> )	t <sub>PHL</sub>	(Note 1) Figure 1	2 1.8	0.9	2.6 2.4	1.5 1.4	μS
Output Settling Time	ts	10V Step to 0.1% (Note 1)	2.5	1.5	2.9	1.9	μS
Break-Before-Make Delay	tOPEN	(Note 1) Figure 3 (Test Circuits)	0.8	0.8	. 1	1	μS
Crosstalk	СТ	(Note 1) Figure 5 (Test Circuits)	70	70	70	70	dB
ΔR <sub>ON</sub> With Applied Voltage	$\Delta R_{ON}$	$-10V \le V_S \le 10V$ , $I_S = 200 \mu A$	1.5	1.5	1.5	1.5	%
Leakage Current (Switch "ON")	I <sub>D</sub> (ON)	V <sub>D</sub> = 10V (Note 1)	20	0.2	20	0.2	nA
Analog Input Range	V <sub>A</sub>	(Note 2)	+11 -15	+ 11 - 15	+ 11 -15	+11 -15	V

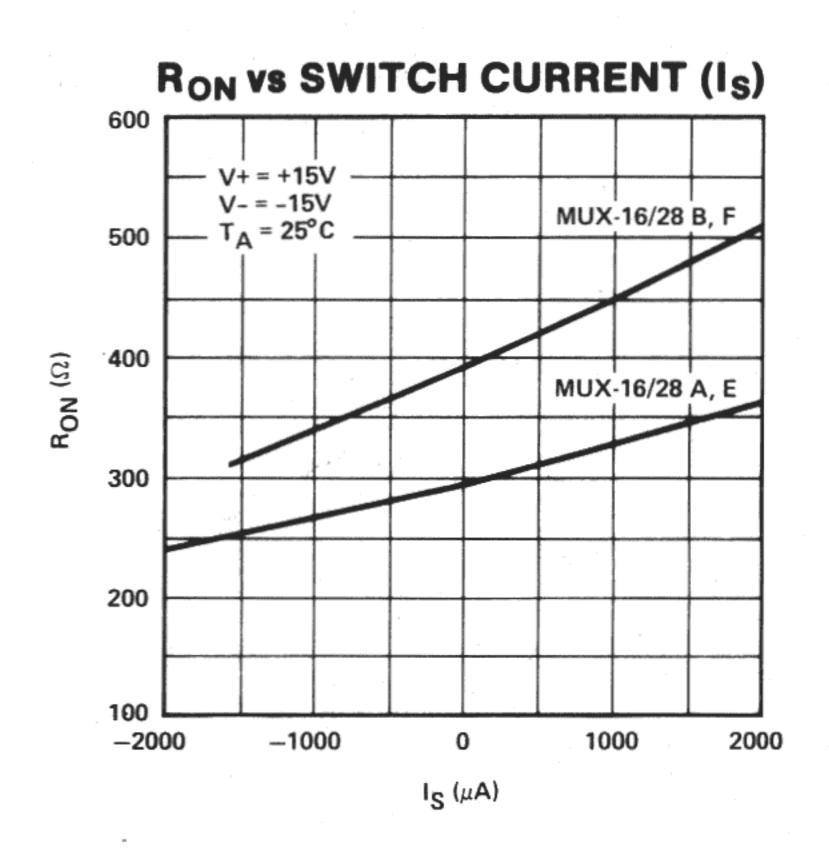
#### NOTES:

- 1. The data shown is extrapolated from measurements made on the packaged devices.
- Guaranteed by R<sub>ON</sub> and leakage current tests.

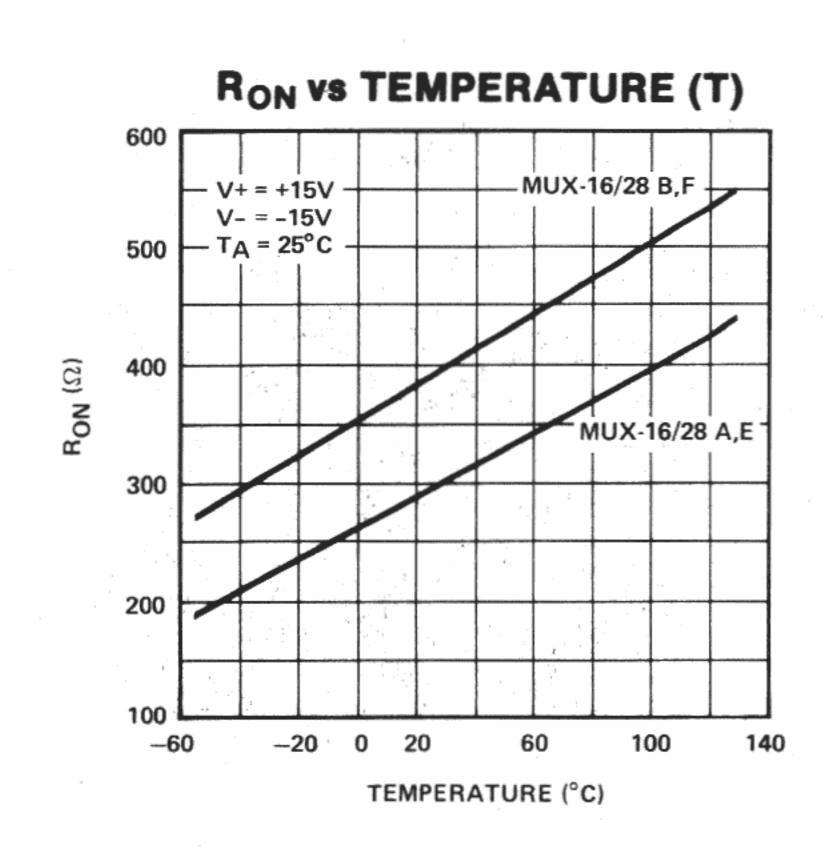
# TYPICAL PERFORMANCE CHARACTERISTICS (apply to all grades, unless otherwise noted.)



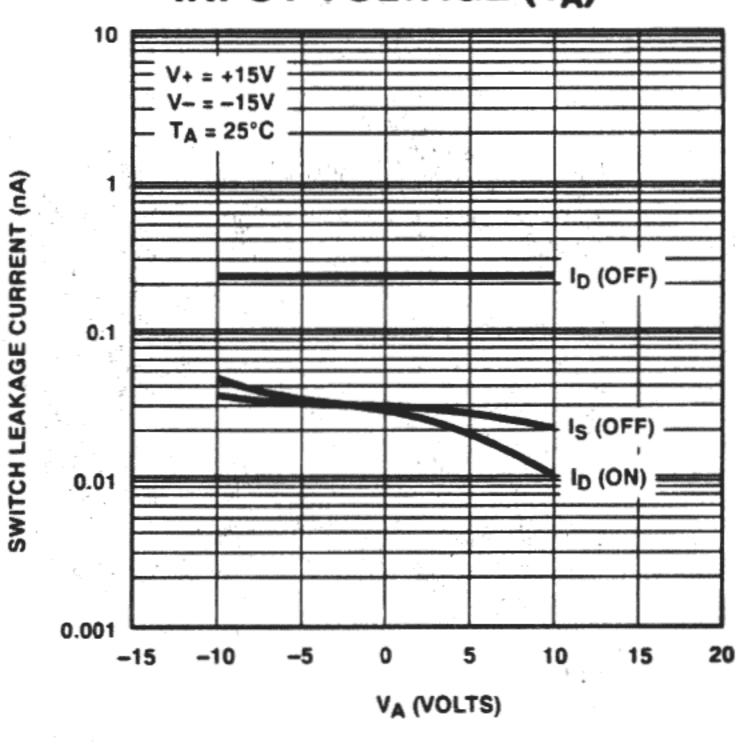




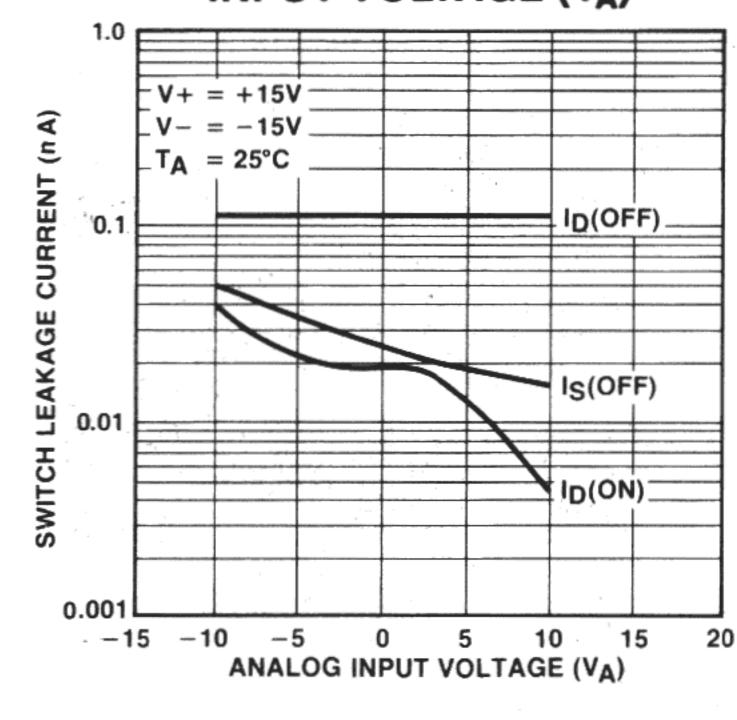
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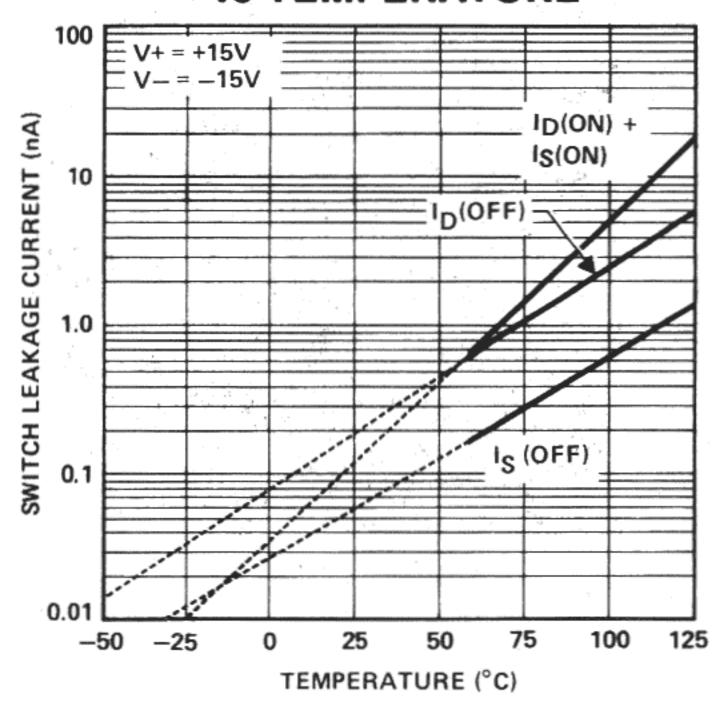
MUX-16 SWITCH LEAKAGE CURRENTS vs ANALOG INPUT VOLTAGE (V<sub>A</sub>)



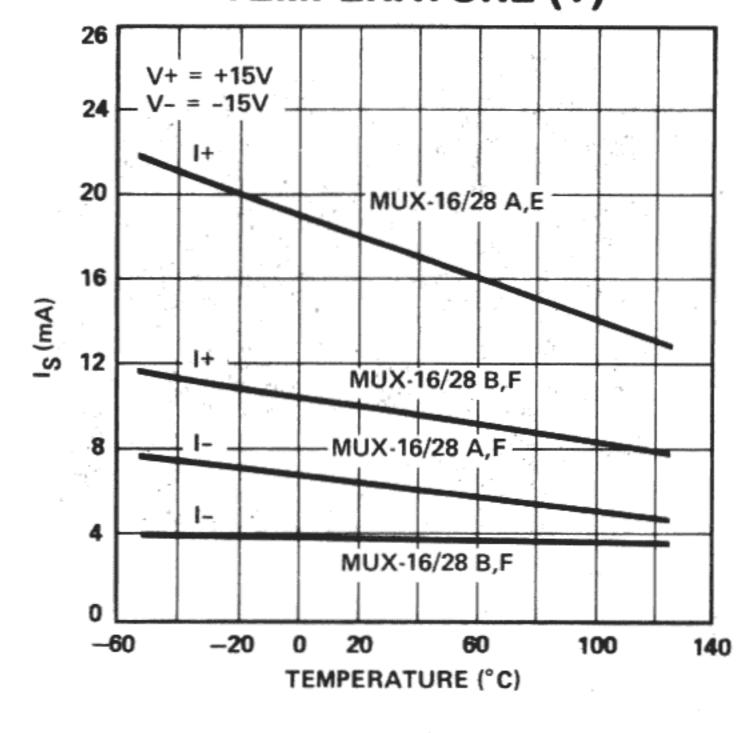
MUX-28 SWITCH LEAKAGE CURRENTS vs ANALOG INPUT VOLTAGE (V<sub>A</sub>)



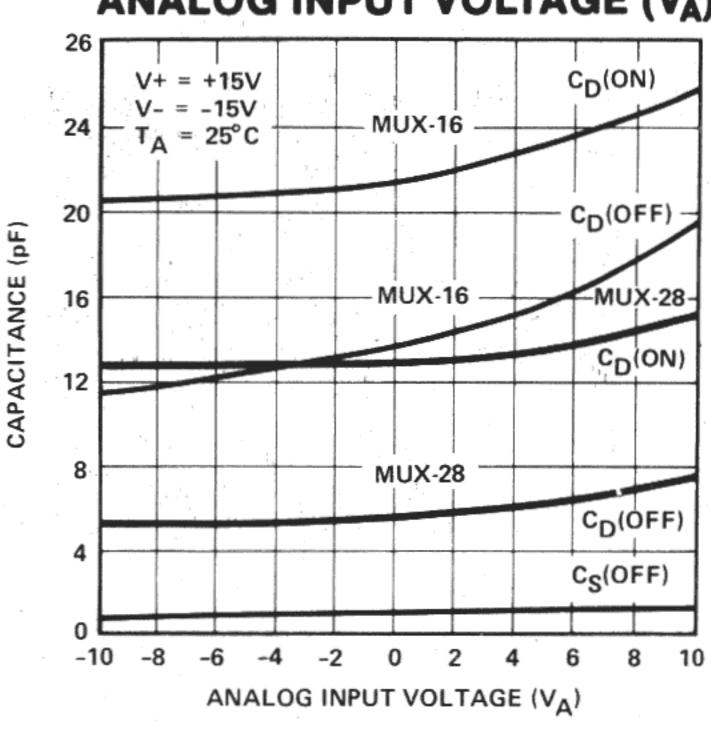
SWITCH LEAKAGE CURRENTS vs TEMPERATURE



SUPPLY CURRENTS vs TEMPERATURE (T)



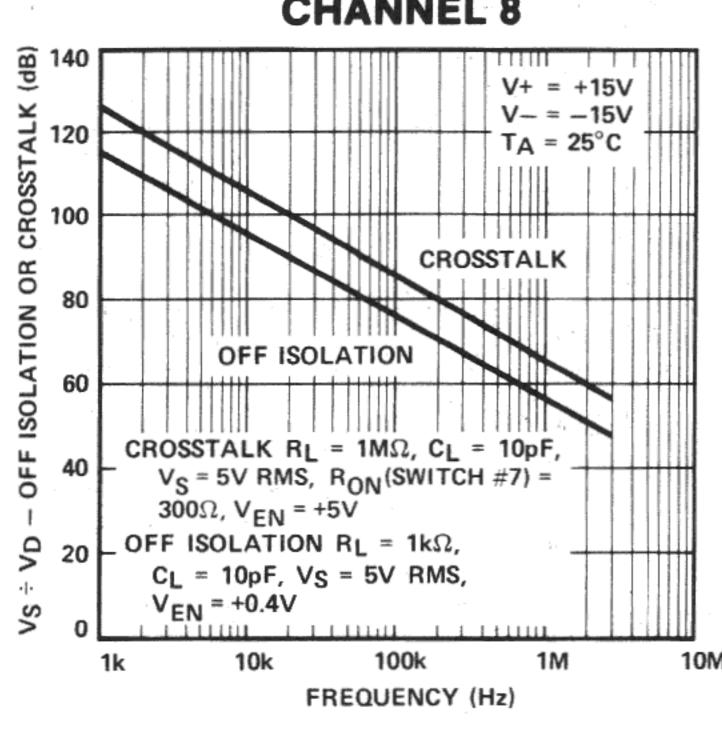
SWITCH CAPACITANCES vs ANALOG INPUT VOLTAGE (V<sub>A</sub>)



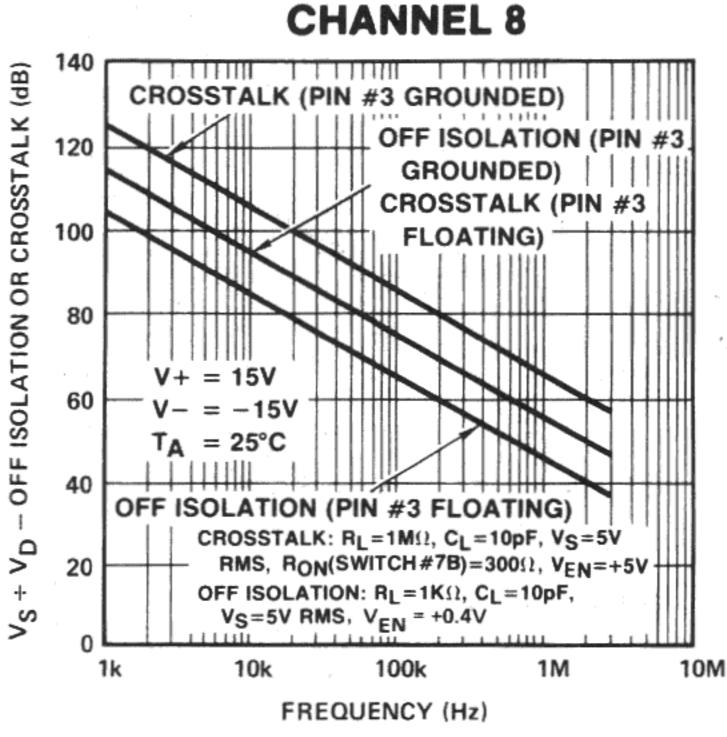
# PMI

# TYPICAL PERFORMANCE CHARACTERISTICS (apply to all grades, unless otherwise noted.)

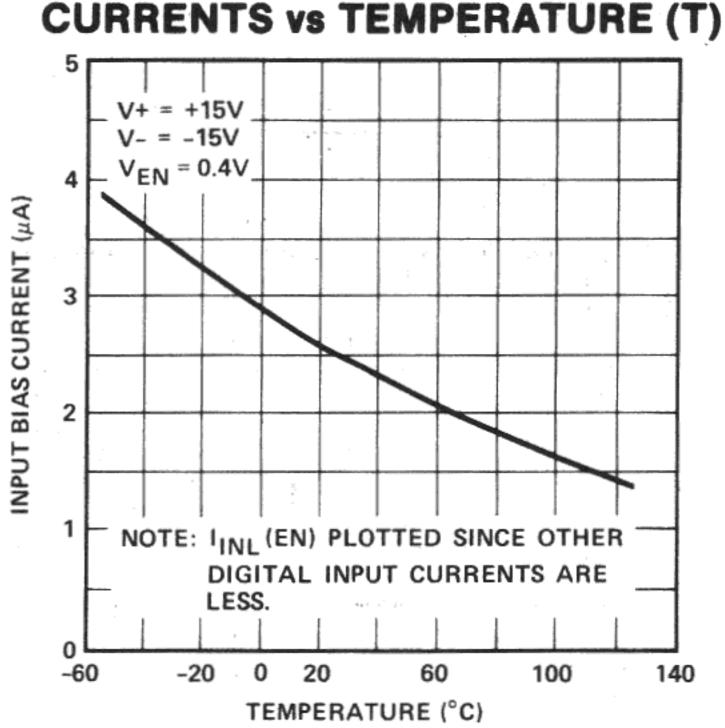
# MUX-16 OFF PERFORMANCE OF CHANNEL 8



# MUX-28 OFF PERFORMANCE OF CHANNEL 8

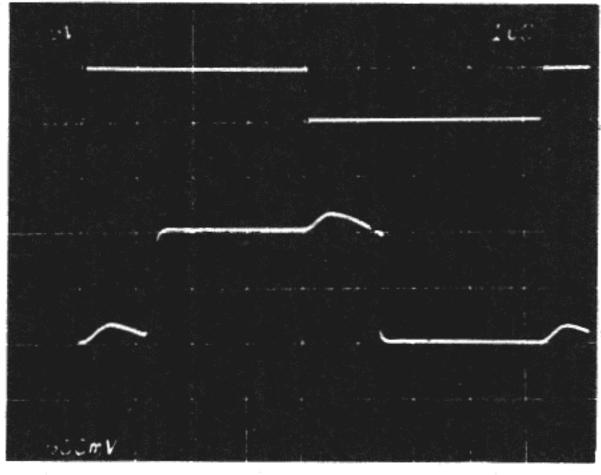


# DIGITAL INPUT BIAS CURRENTS vs TEMPERATURE (T



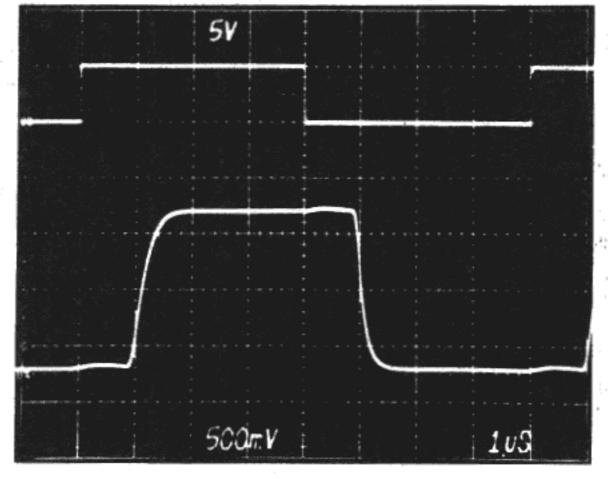
#### **MUX-16 DYNAMIC CHARACTERISTIC CURVES**

### **SMALL-SIGNAL SWITCHING**



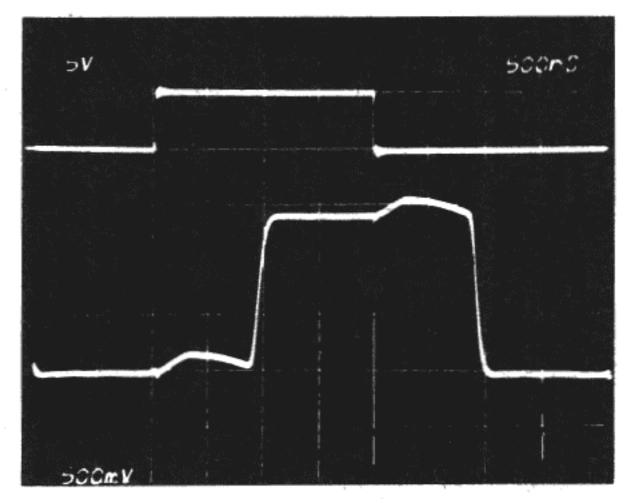
 $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_1 = -500mV$ ,  $V_{16} = +500mV$ 

# SMALL-SIGNAL SWITCHING WITH FILTERING



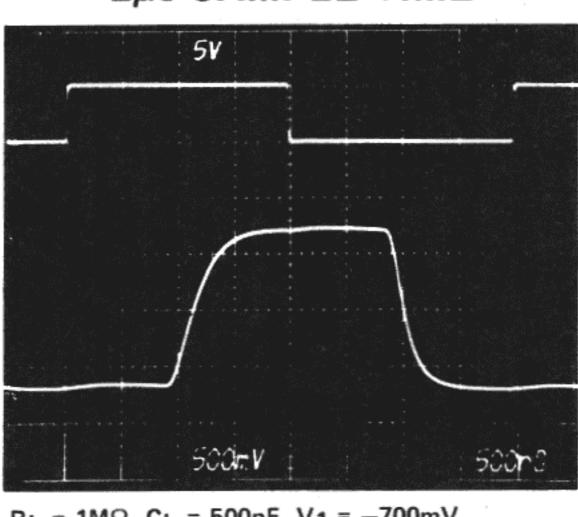
 $R_L = 1M\Omega$ ,  $C_L = 500pF$ ,  $V_1 = -500mV$ ,  $V_{16} = +500mV$ 

# SMALL-SIGNAL SWITCHING WITH 2µs SAMPLE TIME



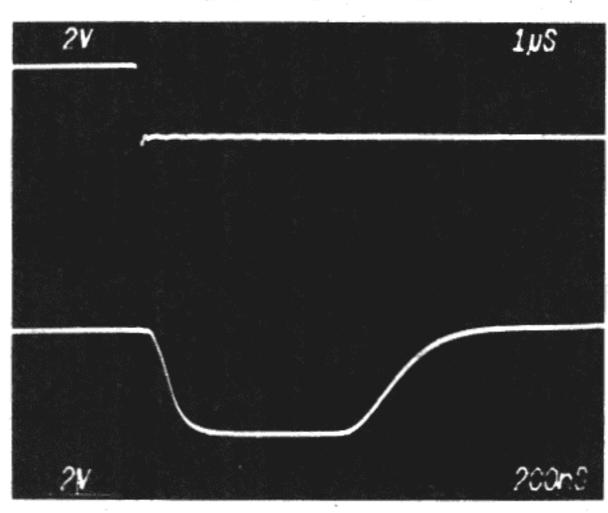
 $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_1 = -700mV$ ,  $V_{16} = +700mV$ 

# SMALL-SIGNAL SWITCHING WITH FILTERING AND 2µs SAMPLE TIME



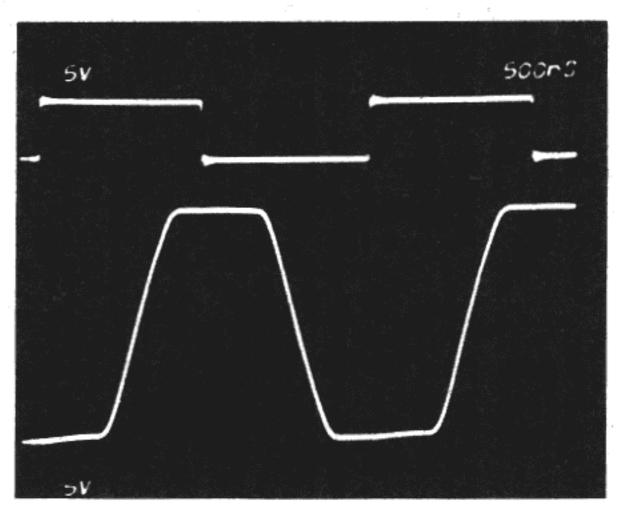
 $R_L = 1M\Omega$ ,  $C_L = 500pF$ ,  $V_1 = -700mV$ ,  $V_{16} = +700mV$ 

# BREAK-BEFORE-MAKE SWITCHING



 $R_L = 1k\Omega$ ,  $C_L = 10pF$ ,  $V_1 = V_{16} = +10V$ 

# LARGE-SIGNAL SWITCHING



 $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_1 = -10V$ ,  $V_{16} = +10V$ 

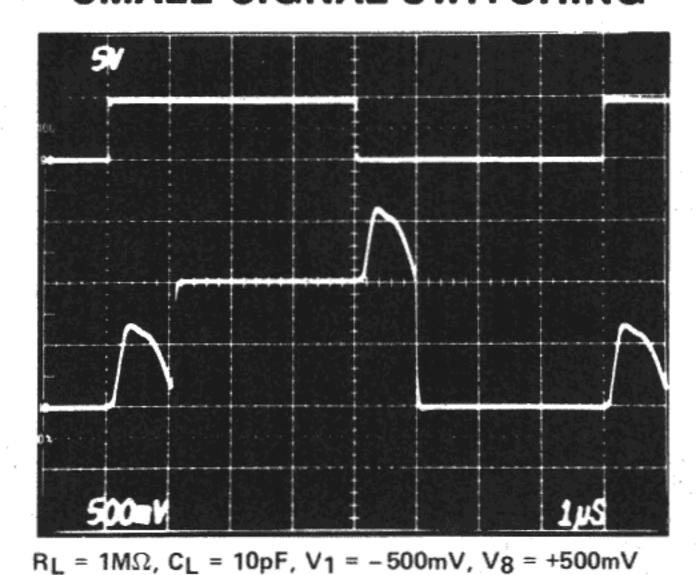
# NOTE:

Top Waveforms: Digital Input 5V/Div

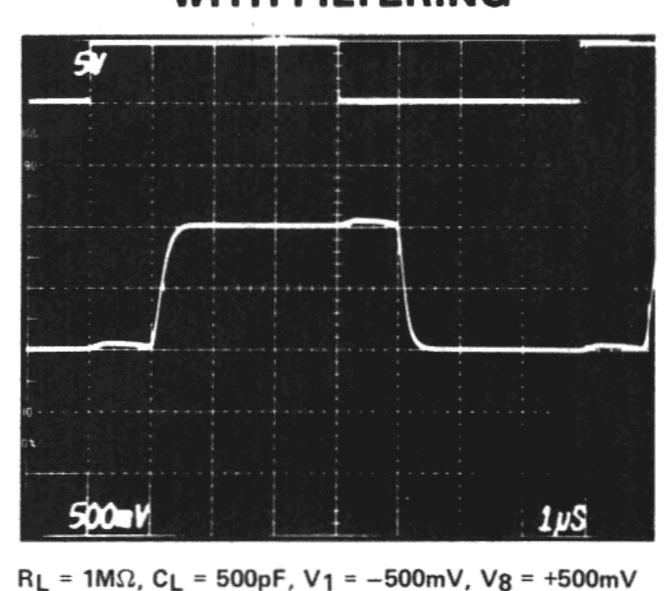
Bottom Waveforms: Multiplexer Output (V<sub>D</sub>)

# MUX-28 DYNAMIC CHARACTERISTIC CURVES

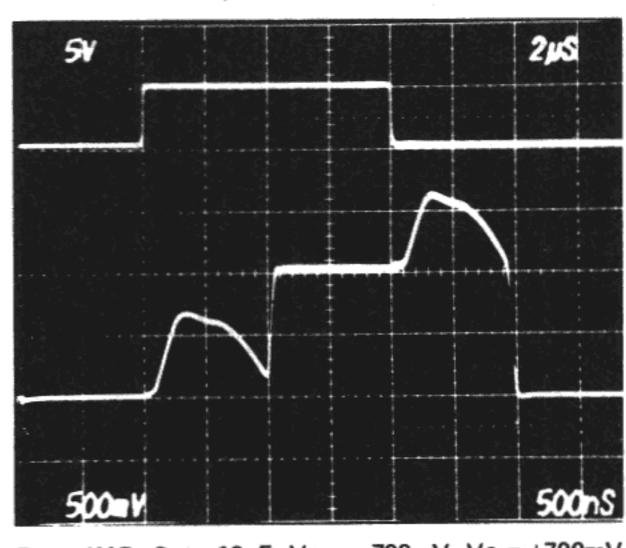
# **SMALL-SIGNAL SWITCHING**



# **SMALL-SIGNAL SWITCHING** WITH FILTERING

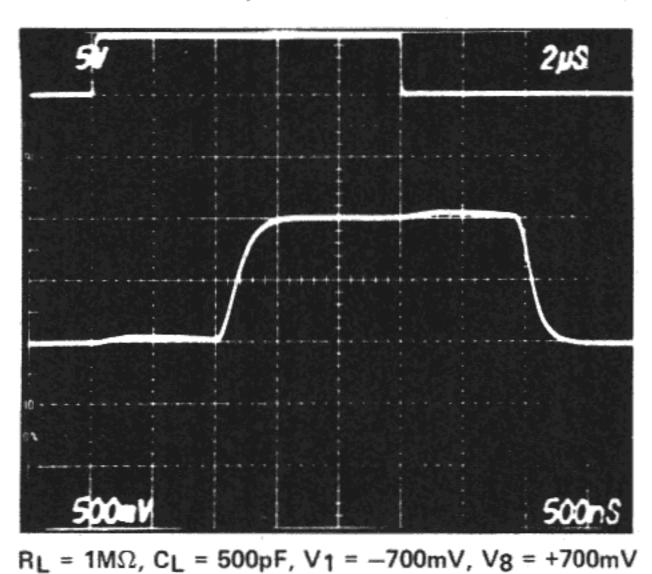


**SMALL-SIGNAL SWITCHING** WITH 2µs SAMPLE TIME

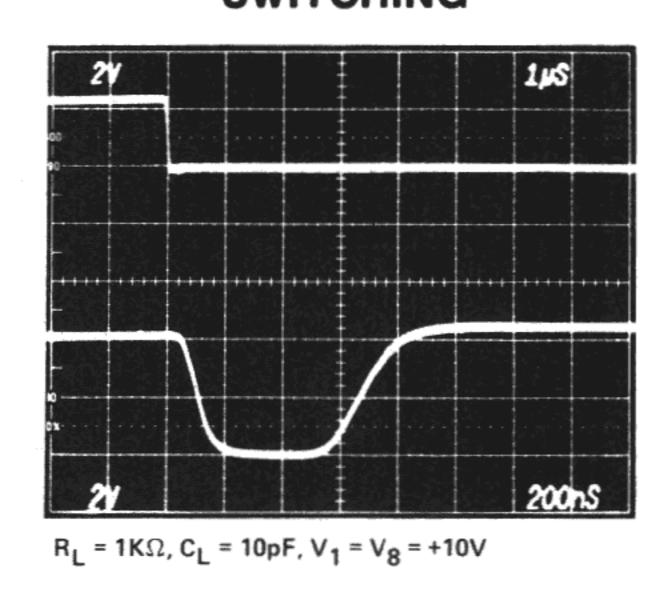


 $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_1 = -700mV$ ,  $V_8 = +700mV$ 

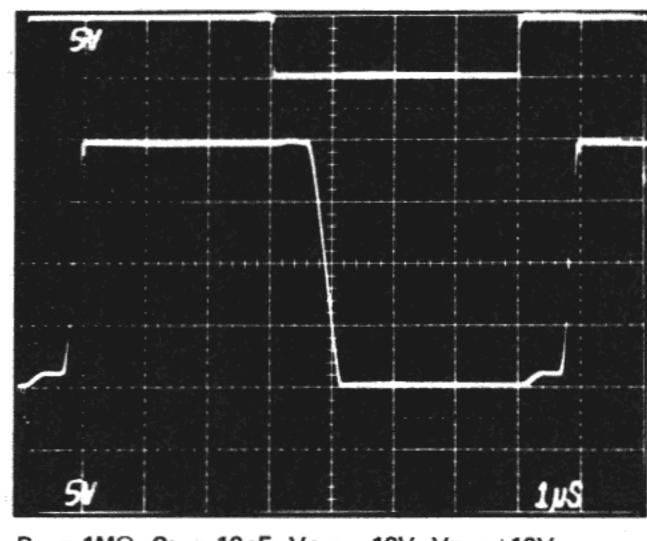
# **SMALL-SIGNAL SWITCHING** WITH FILTERING AND 2.5 µs SAMPLE TIME



**BREAK-BEFORE-MAKE SWITCHING** 



LARGE-SIGNAL SWITCHING



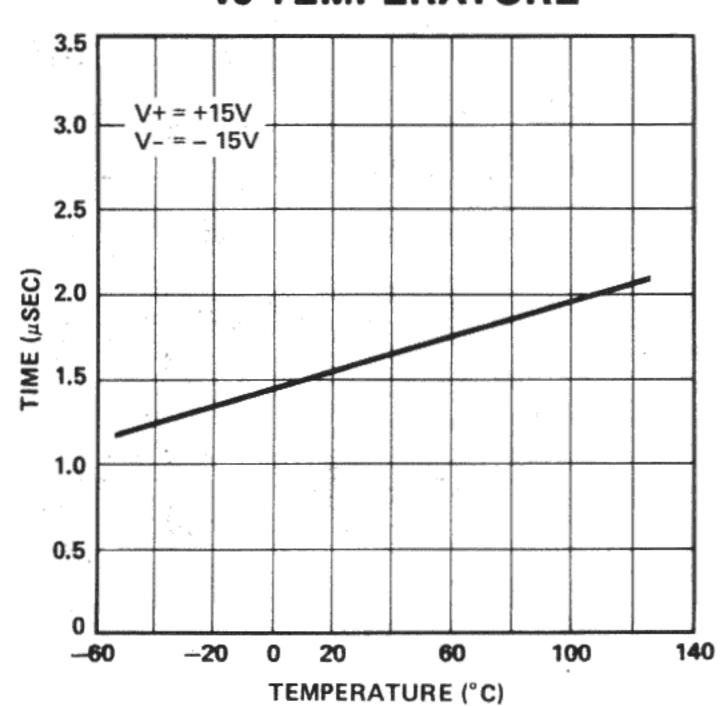
 $R_L = 1M\Omega$ ,  $C_L = 10pF$ ,  $V_1 = -10V$ ,  $V_8 = +10V$ 

# NOTE:

Top Waveforms: Digital Input 5V/Div Bottom Waveforms: Multiplexer Output (V<sub>D</sub>)

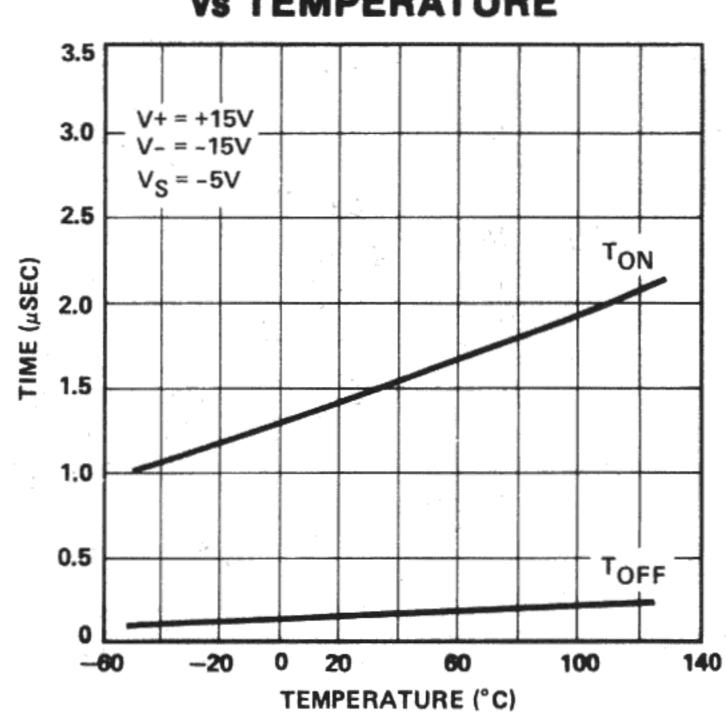
# TYPICAL PERFORMANCE CHARACTERISTICS (apply to all grades, unless otherwise noted.)

# TRANSITION TIME **vs TEMPERATURE**



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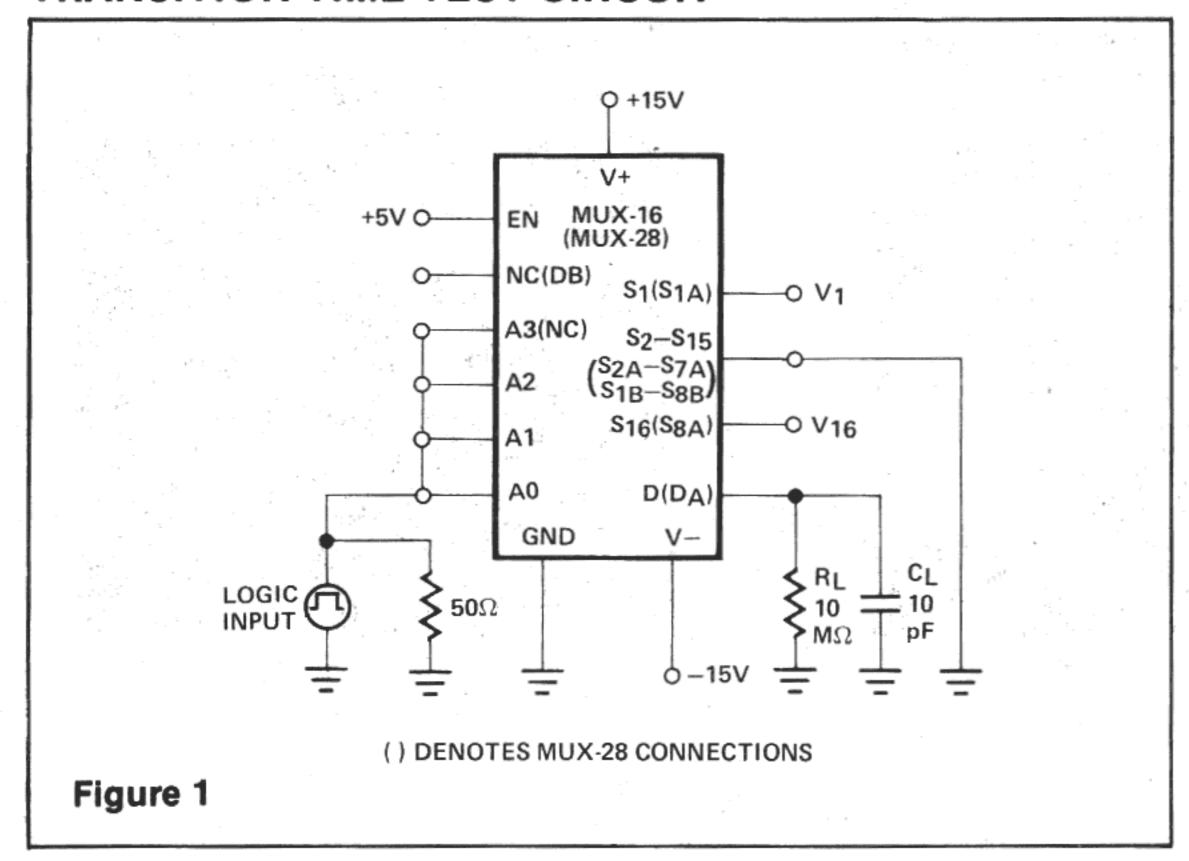
# **ENABLE DELAY TIME VS TEMPERATURE**



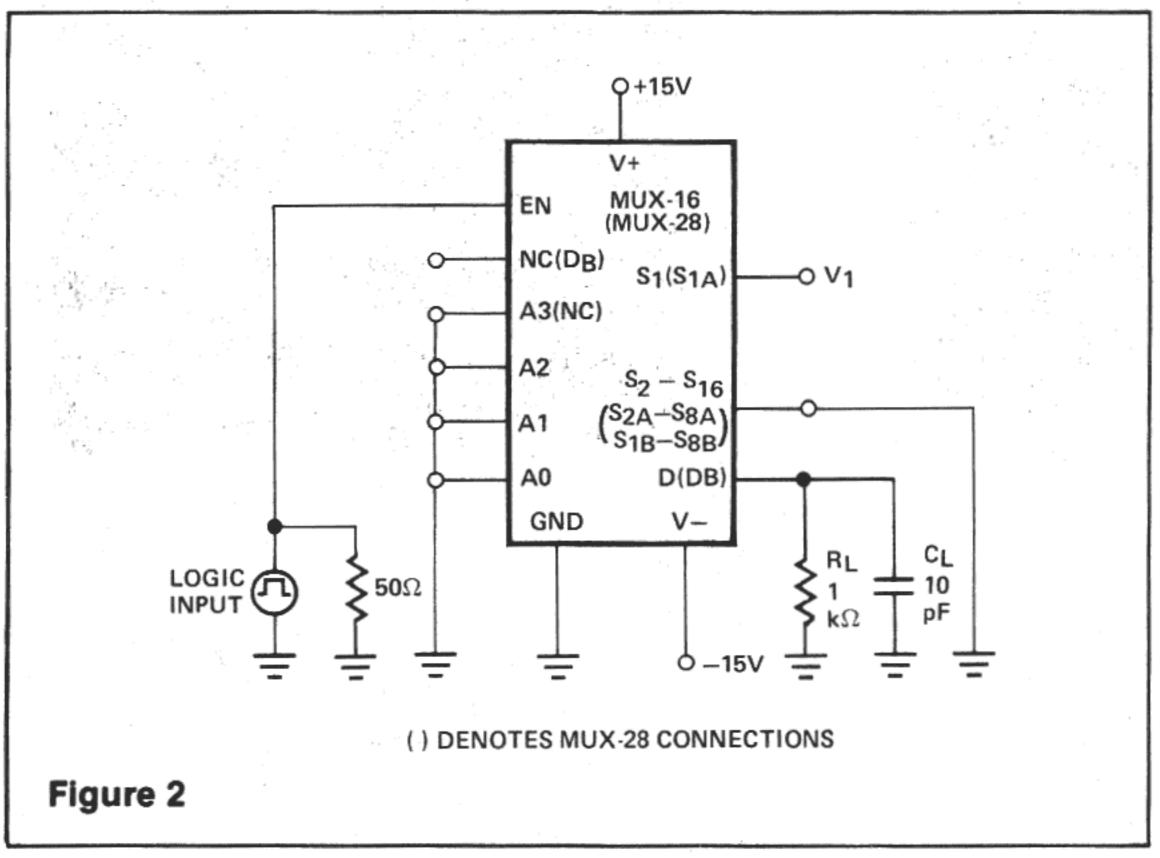
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# A.C. TEST CIRCUITS

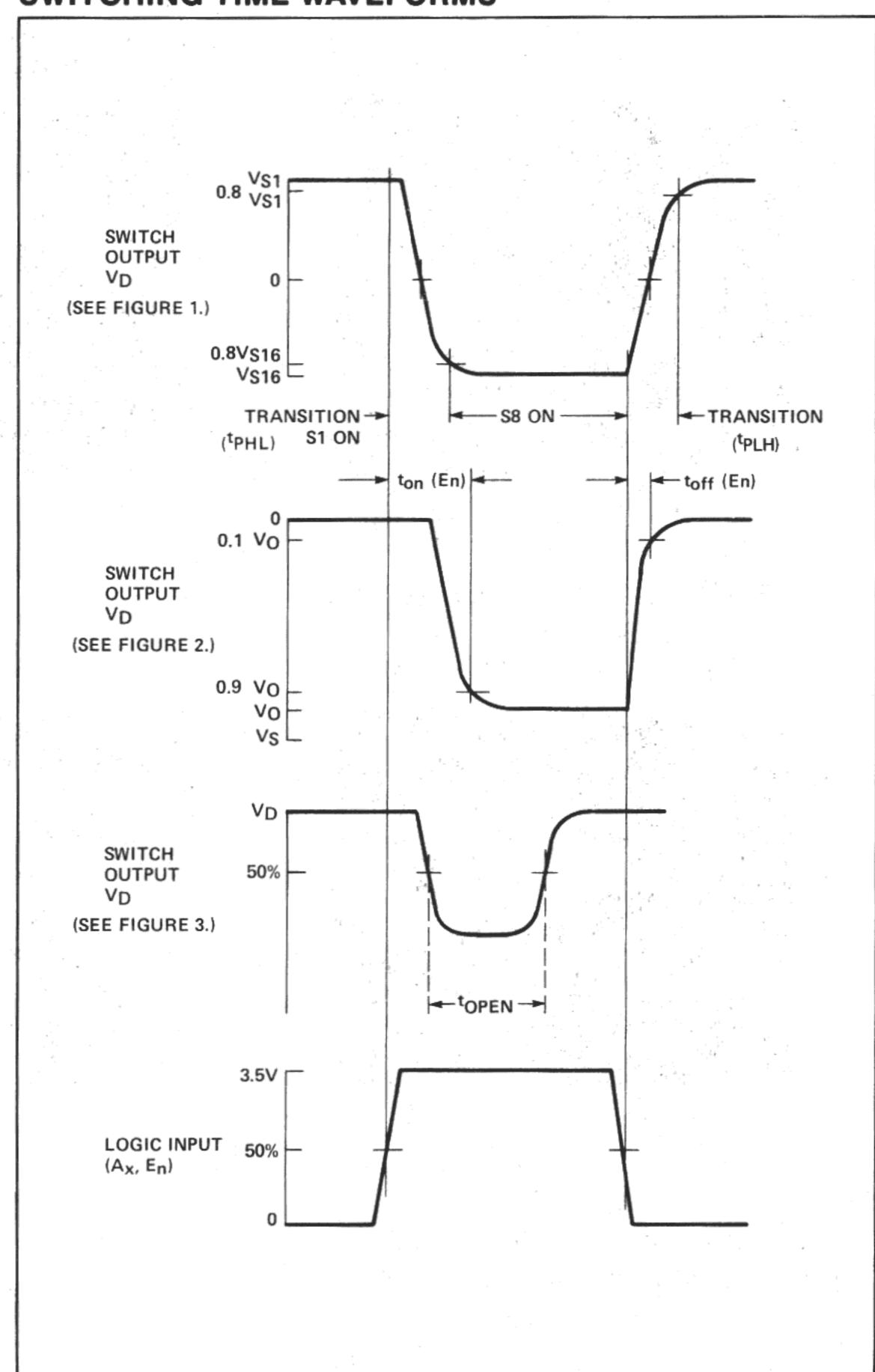
#### TRANSITION TIME TEST CIRCUIT



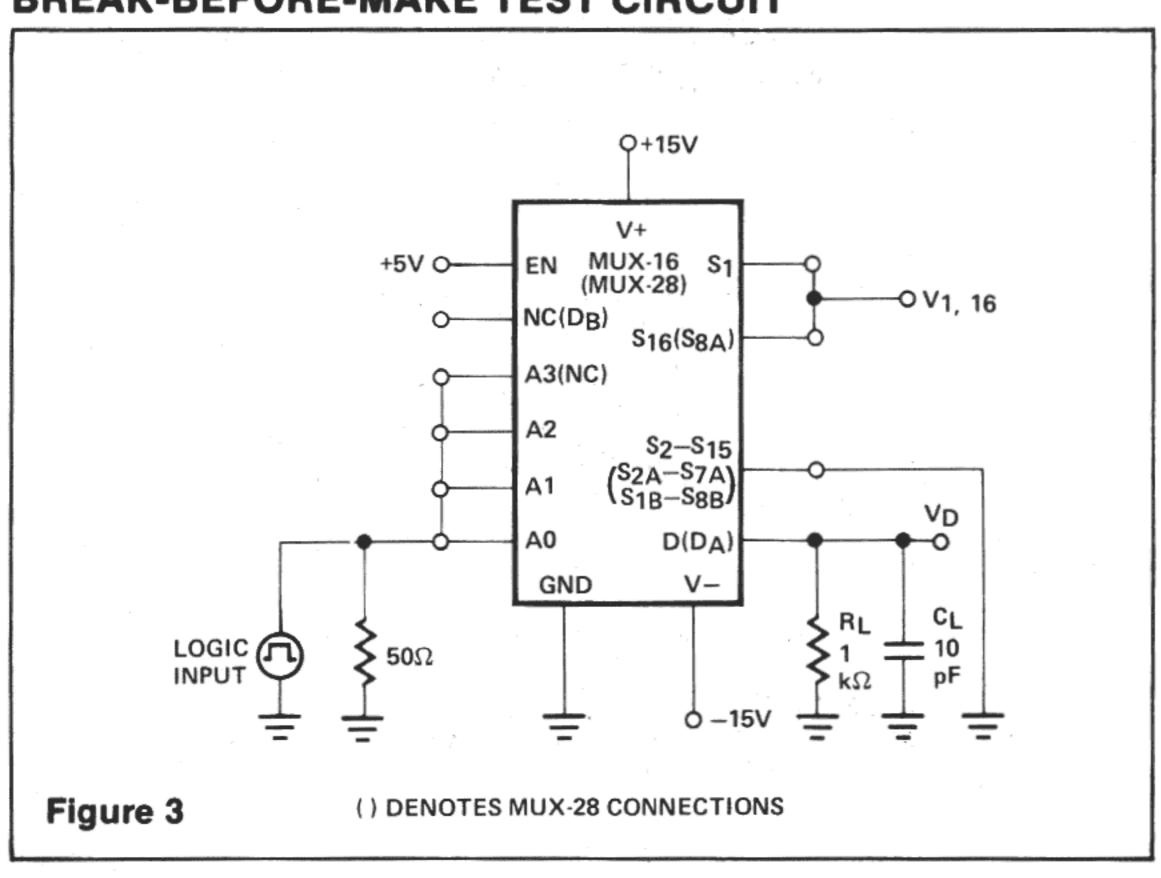
#### **ENABLE DELAY TIME TEST CIRCUIT**



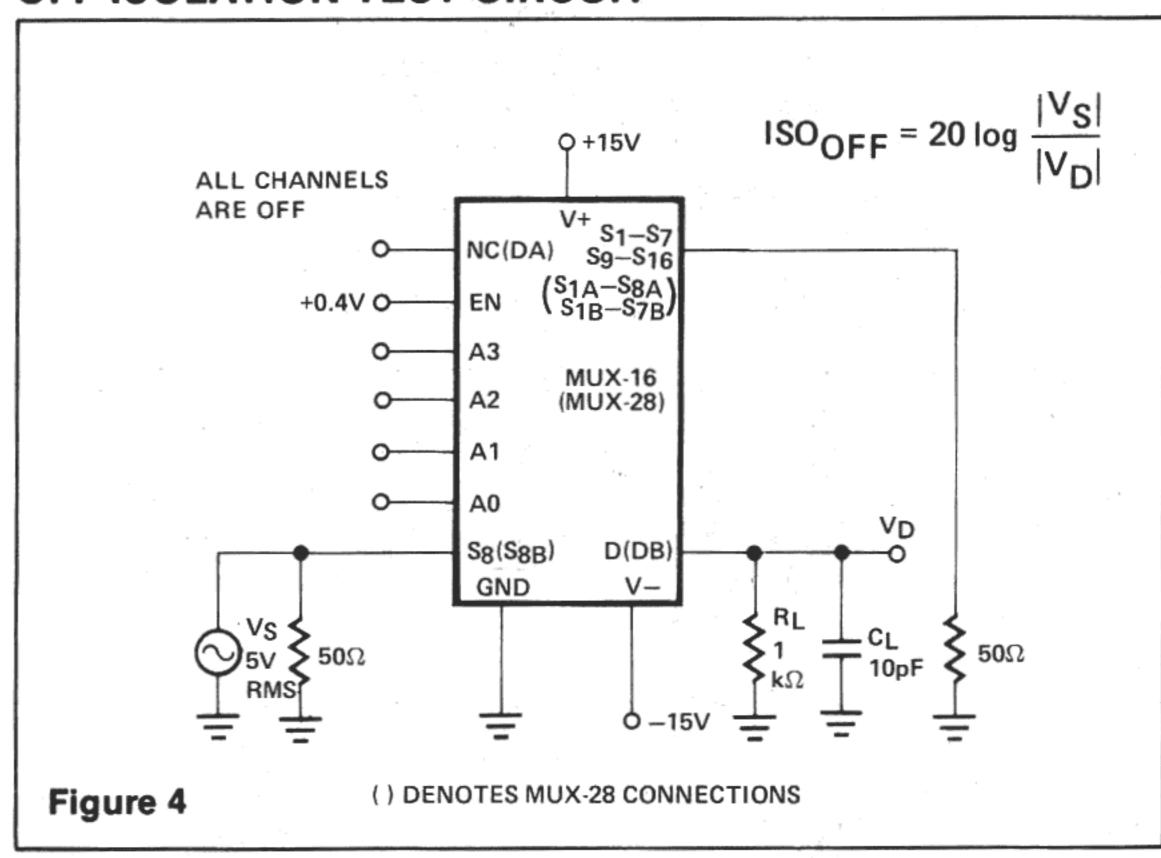
# **SWITCHING TIME WAVEFORMS**



#### **BREAK-BEFORE-MAKE TEST CIRCUIT**

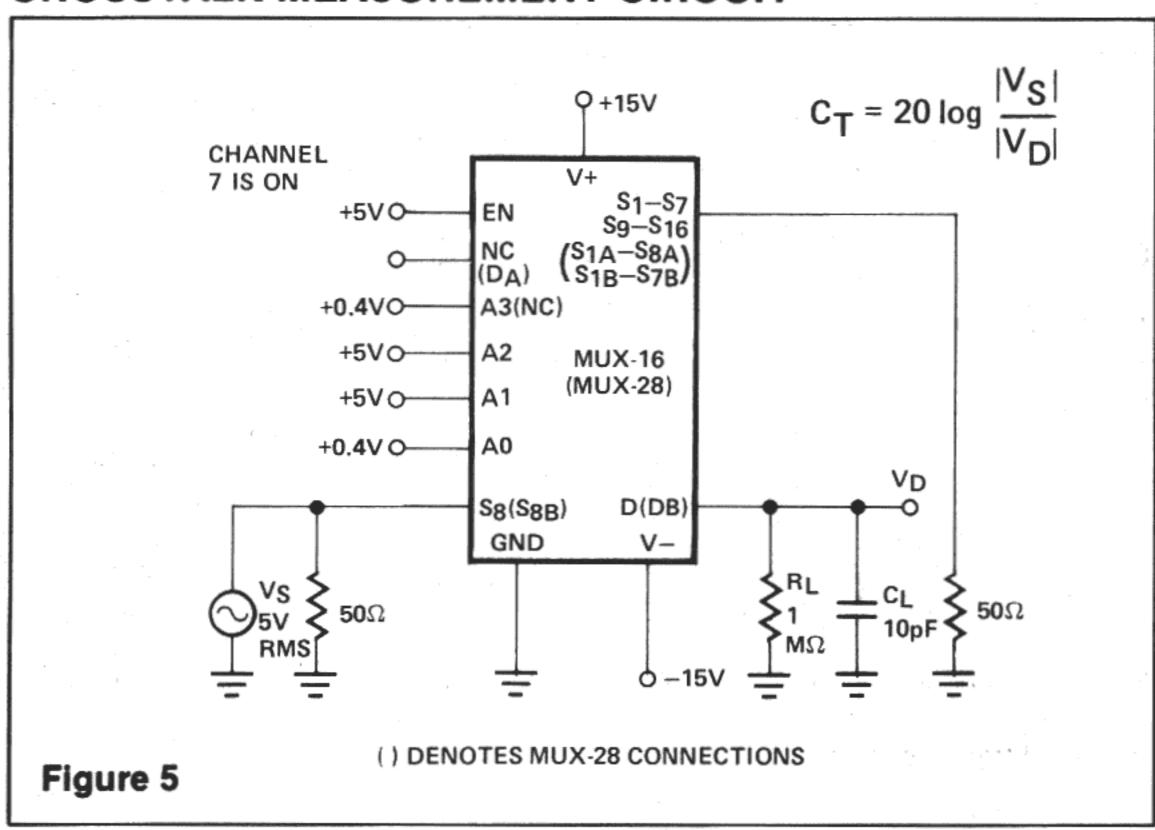


#### OFF ISOLATION TEST CIRCUIT





#### CROSSTALK MEASUREMENT CIRCUIT



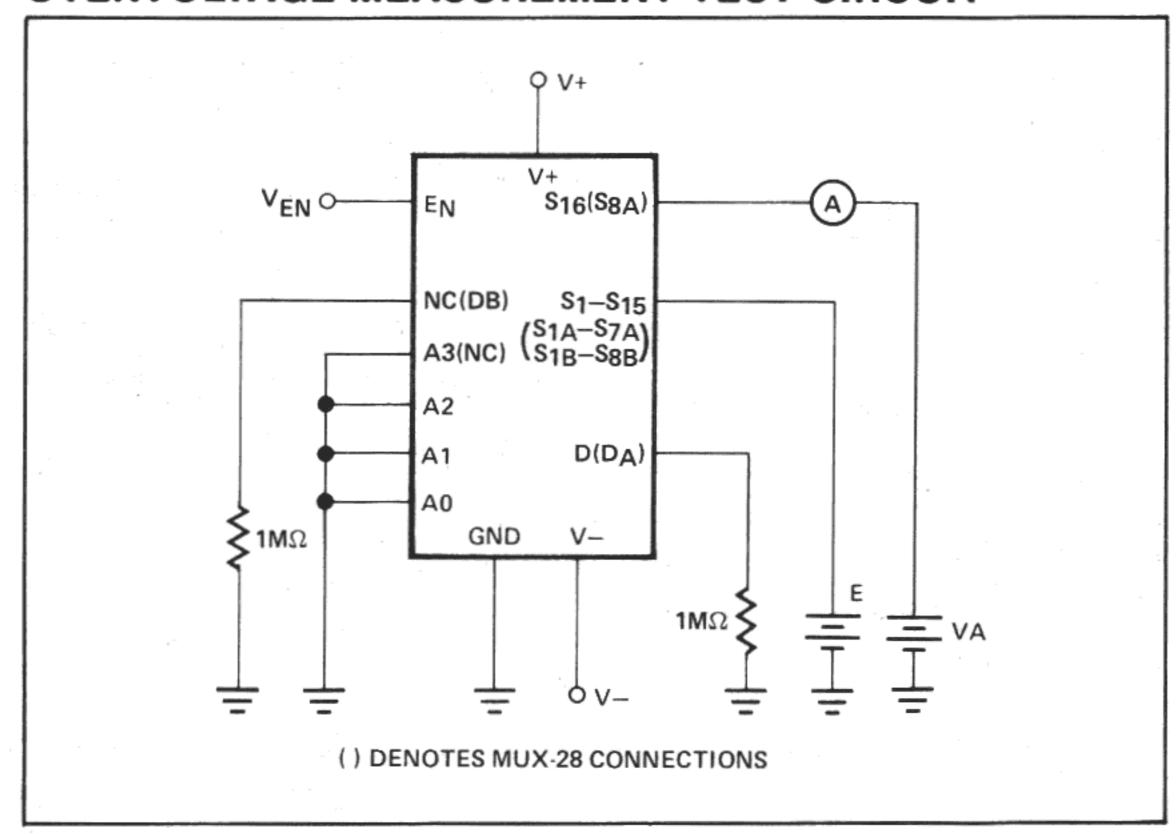
### **APPLICATIONS INFORMATION**

These analog multiplexers employ ion-implanted JFETs in a switch configuration designed to assure break-before-make (B.B.M.) action. The turn-off time is much faster than the turn-on time to guarantee B.B.M. over the full operating temperature and input voltage range. Fabricated with JFET processing rather than CMOS, special handling is not necessary to prevent damage to this multiplexer. Because the digital inputs only require a 2.0V logic "1" input level, power-consuming pullup resistors are not required for TTL compatibility to insure break-before-make switching as is most often the case with CMOS multiplexers. The digital inputs utilize PNP input transistors where input current is maximum at the logic "0" level and drops to that of a reverse-biased diode (about 10nA) as the input voltage is raised above ≈ 1.4V.

The "ON" resistance,  $R_{ON}$  of the analog switches is constant over the wide input voltage range of -15V to +11V with  $V_{SUPPLY}=\pm15V$ . The overvoltage and supply-loss V-I characteristics shown indicate typical performance when the multiplexer is subjected to abnormal signals. For normal operation, however, positive input voltages should be restricted to 11V (or 4V less than the positive supply). This assures that the  $V_{GS}$  of an OFF FET switch remains greater than its  $V_P$ , preventing that channel from being falsely turned ON.

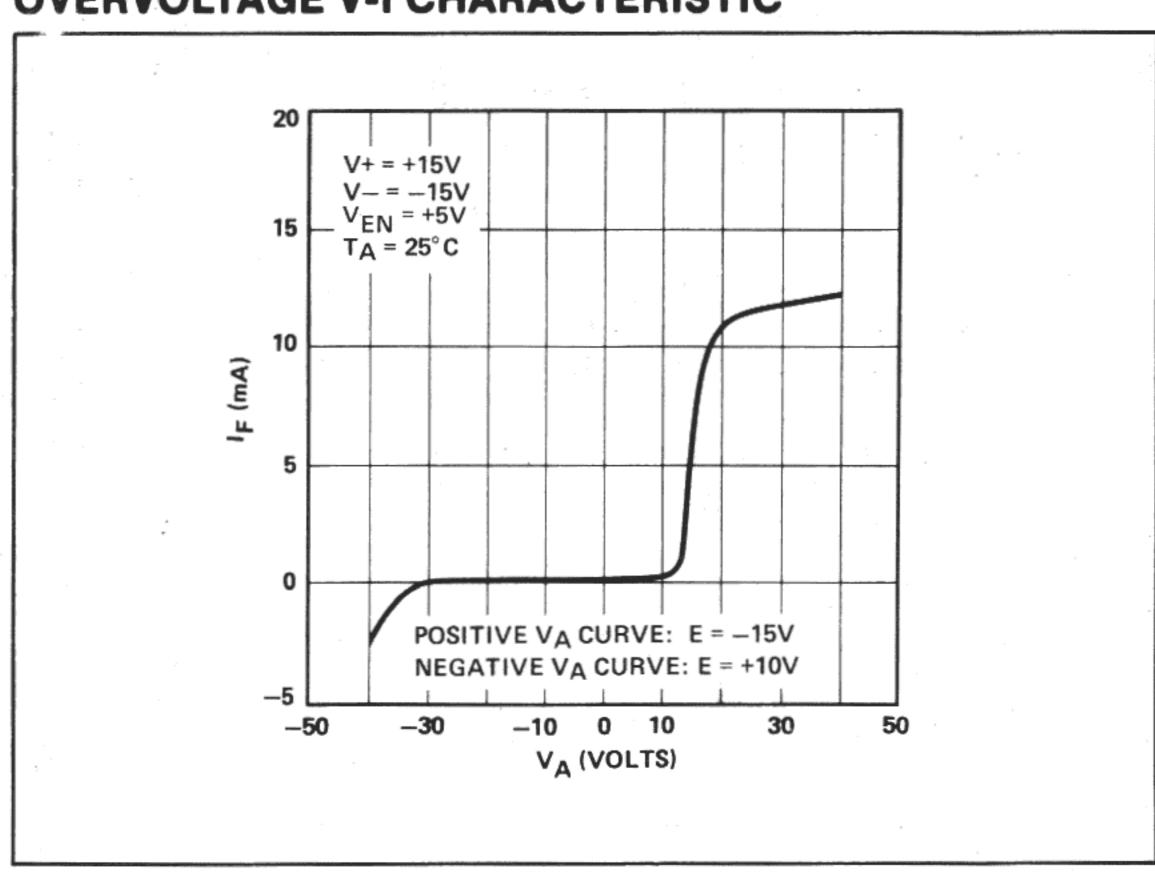
When operating with negative input voltages, the gate-to-channel diode will be turned on if the voltage drop across an ON switch exceeds -0.6V. While this condition will cause an error in the output, it will not damage the switch. In lab tests, the multiplexer output has been loaded with a  $0.01\mu F$  capacitor in the circuit of Figure 1. With  $V_1 = -10$ V and  $V_{16} = +10$ V, the logic input was driven at a 1kHz rate. The positive-going slew rate was 0.3V/ $\mu Sec$  which is equivalent to a normal  $I_{DSS}$  of 3mA. The negative-going slew rate was 0.7V/ $\mu Sec$  which is equivalent to a "reverse"  $I_{DSS}$  of 7mA. Note that when switch one (1) is first turned ON it has a drop of -20V across its terminals. In spite of that fact, the current is limited to approximately twice its normal  $I_{DSS}$ .

#### **OVERVOLTAGE MEASUREMENT TEST CIRCUIT**

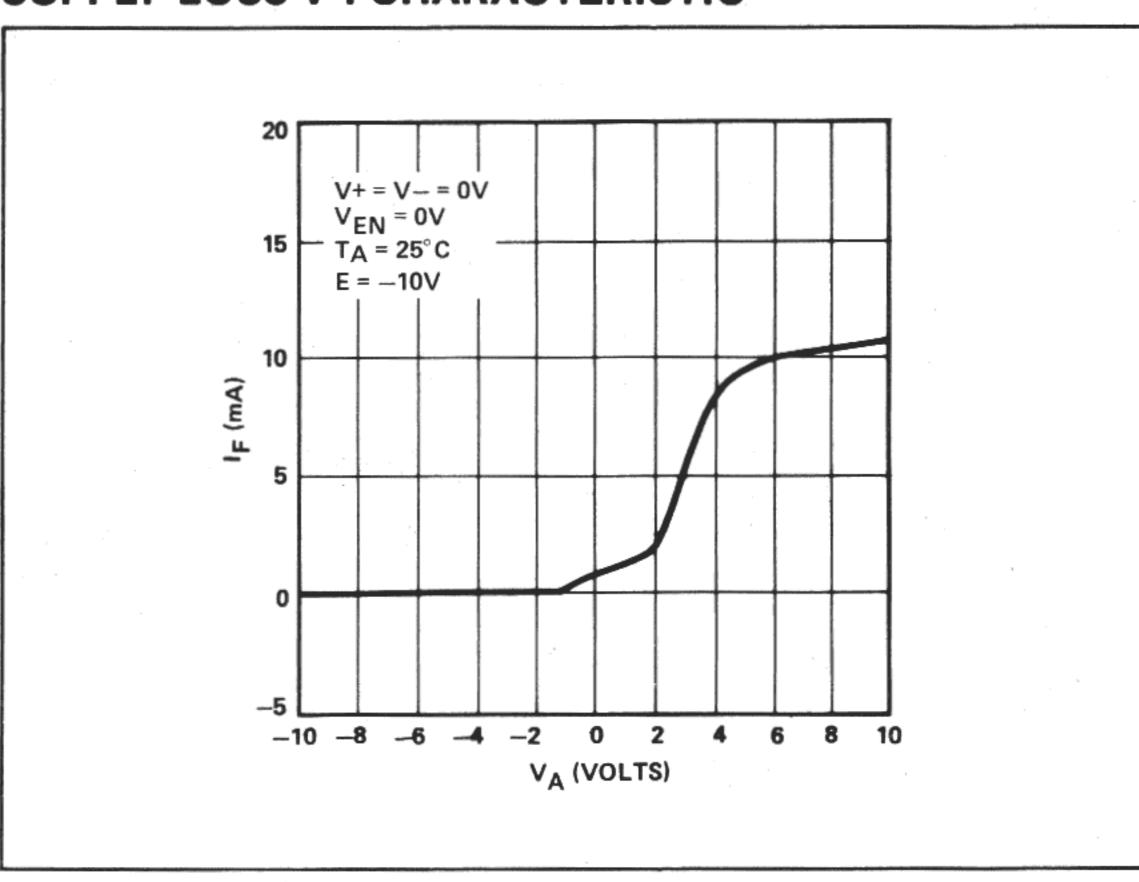


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#### **OVERVOLTAGE V-I CHARACTERISTIC**

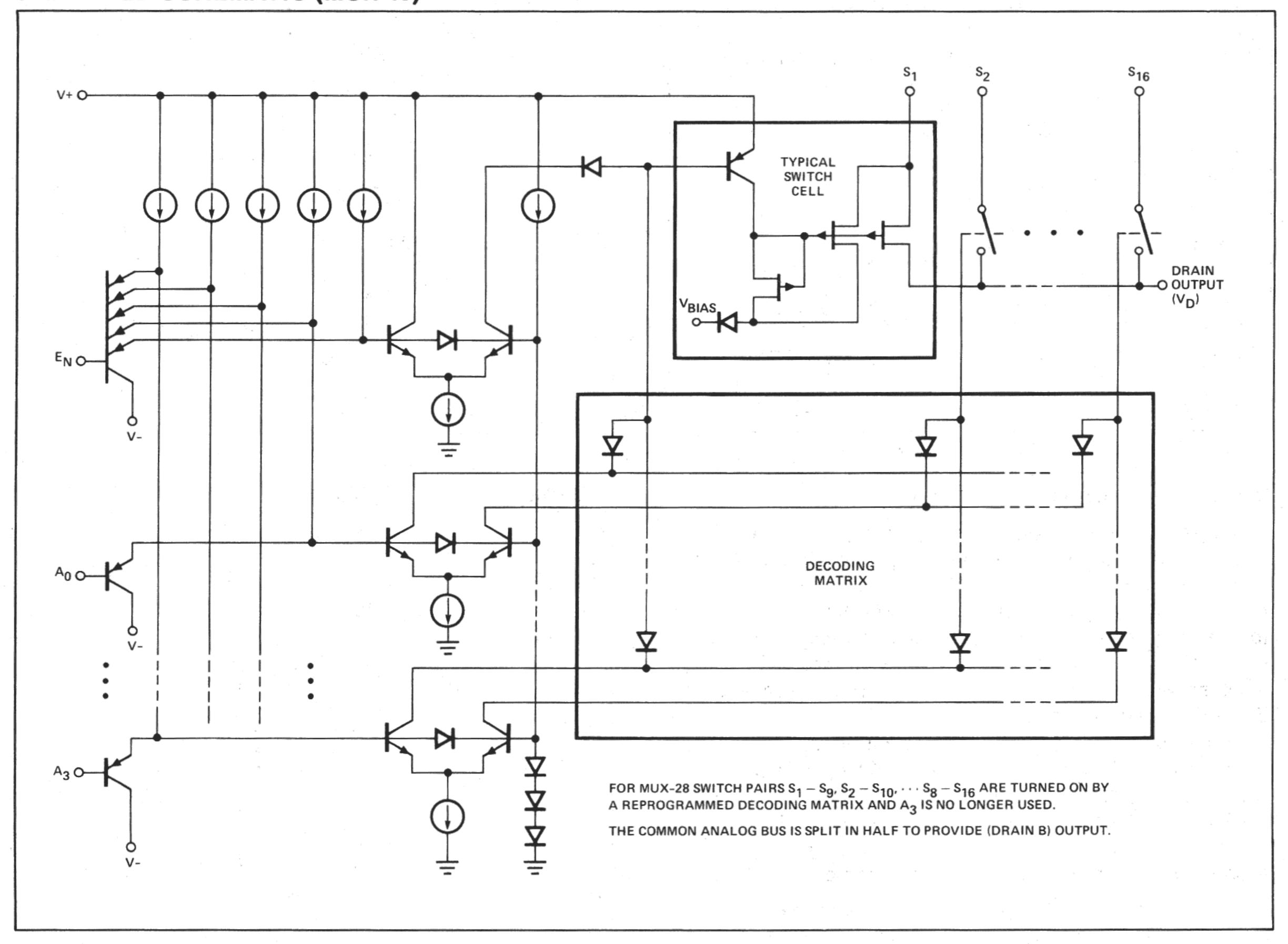


#### SUPPLY-LOSS V-I CHARACTERISTIC





# SIMPLIFIED SCHEMATIC (MUX-16)



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Precision Monolithics Inc.

# INTRODUCTION

Analog multiplexers and switches find applications in data acquisition, metrology, telemetry, process control and telephony systems. Multiplexers are multiple analog switches which share a common output. An on-chip address decoder selects the appropriate input by means of a binary code. All channels may be deactivated by an enable/disable control pin.

In the past multiplexers/switches have been manufactured with hybrid, monolithic CMOS or dielectrically isolated CMOS technologies. The merging of ion implant techniques with the standard bipolar process creates a fourth technological alternative — the bipolar-JFET process. High-quality ion implanted p-channel FET's can now be compatibly processed with bipolar devices.

The cost of hybrid devices limits their use to applications which require the extremely low "Ron" resistance made possible by discrete FET's. MOS technologies are inherently plagued by SCR "latch up" problems and analog signal overvoltage destruction. The use of buried layers and expensive dielectric isolation processing can eliminate the SCR failure mode, but the overvoltage blowout problems can be solved only by adding large series input resistance with each switch. This increases system errors since the equivalent "Ron" may typically be over 1000 ohms.

JFET switches have no SCR "latch up" tendency and can withstand analog input overvoltages while maintaining low "R<sub>ON</sub>" resistance. In addition, the special handling required with CMOS devices is not necessary with JFET switches.

In selecting analog multiplexers, attention must be paid to several key specs. Break-before-make switching insures no two-channel inputs are simultaneously connected. This prevents input sensor damage and misoperation. Acquiring analog input signals within a specified time and error band are primary concerns affected by "Ron" resistance and "Cout" capacitance specifications. A low "Ron" insures minimum signal attenuation and maximum accuracy. The "Cout" capacitance forms on R-C time constant

with "R<sub>ON</sub>" placing fundamental limits on signal acquisition time. Low "R<sub>ON</sub>" and "C<sub>OUT</sub>" insures minimum elapsed time between the channel select command and the acquisition of data to within a specified error band. High cross talk and off isolation specifications prevent unselected input signals from affecting the signal path.

PMI offers a wide selection of single-ended and differential multiplexers and switches. Sixteen and eight-channel multiplexers as well as differential eight and four-channel devices are available. Dual and Quad SPST switches in normally closed and open configurations are also available. All devices are pin-for-pin replacements for many industry standard CMOS devices.

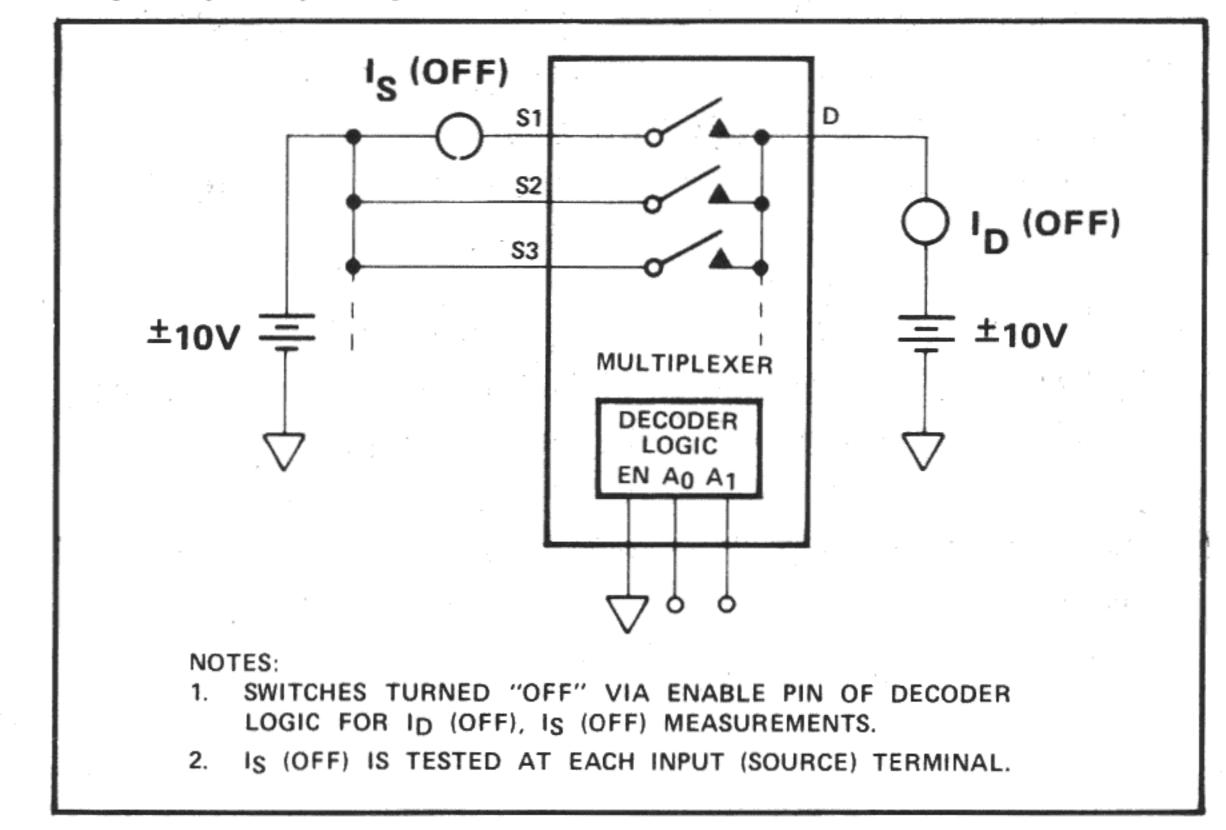
Two new additions to PMI's analog switch product offering are the SSM-2402 and SSM-2412. These dual channel devices provide *click-free* switching in audio applications.

# **DEFINITIONS**

Analog Current Range (I<sub>A</sub>, I<sub>S</sub>) — The minimum range of currents the switch is capable of conducting in the ON state without degrading ON resistance. It is measured as the value of conduction current that does not cause more than a doubling of the R<sub>ON</sub> value for the product grade.

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# I<sub>D(OFF)</sub>, I<sub>S(OFF)</sub> Test Condition Definitions





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Analog Input Leakage Current (Is(OFF)) — The algebraic sum of diode current losses from an OFF-channel source input to the power supplies, ground and through the channel. Specified as an absolute value, as the direction of current flow is not predictable.

Analog Output Leakage Current (I<sub>D(OFF)</sub>) — The algebraic sum of diode current losses from an OFF-channel "D" output to the power supplies, ground and through the channel. Specified as an absolute value, as the direction of current flow is not predictable.

Analog Output-To-Input Capacitance (C<sub>DS(OFF)</sub>)

— The equivalent capacitance which shunts an open switch effectively between "S" and "D" output.

Analog Input Capacitance (C<sub>S(ON)</sub>) — The capacitance between an analog "S" input and ground with the channel ON.

Analog Input Capacitance (C<sub>S(OFF)</sub>) — The capacitance between an analog "S" input and ground with the channel OFF.

Analog Output Capacitance (C<sub>D(OFF)</sub>) — The capacitance between the analog (DRAIN) output and ground with the channel OFF. High-frequency transmission and output settling time characteristics are highly influenced by this parameter in conjunction with R<sub>ON</sub>.

Analog Output Capacitance (C<sub>D(ON)</sub>) — The capacitance between the analog "D" output and ground with the channel ON.

Analog Voltage Range ( $V_A$ ) — The range of analog-voltage amplitudes, with-respect-to ground, over which the analog switch operates (ON/OFF) within the R<sub>ON</sub> and leakage specifications —  $I_{S(OFF)}$ ,  $I_{D(OFF)}$  and  $I_{D(ON)} + I_{S(ON)}$ .

Break-Before-Make Delay (topen) — The elapsed time between the turn-off of one analog input and the subsequent turn-on of another input as determined by the appropriate instantaneous change in the digital input code for both inputs measured between the outputs' 50% transition points.

Channel Capacitance (Css(OFF), CDD(OFF)) — The capacitance between the D(S) terminals of any two channels.

Charge Transfer (Q) — Charge transfer appears as a voltage step (pedestal) on the output capacitor after switch turn OFF. The undesirable charge AC couples directly from the logic-control driver to the switch contact.

Crosstalk (CT) — The proportionate amount of cross-coupling from an analog input channel to another output channel, expressed in dB.

Digital Input Capacitance (CDIG) — The capacitance between a digital input and ground.

**Insertion Loss** — Insertion loss measures the amount of signal power absorbed by the switch ON resistance at a given measurement frequency. Insertion loss is defined in decibels as a ratio of the output-voltage amplitude  $(V_D)$  versus the input-voltage amplitude  $(V_S)$  with a specified load impedance.

Insertion Loss (dB) = 20 
$$log \frac{|V_D|}{|V_S|}$$

At low frequencies this equation simplifies to:

Insertion Loss (dB) = 20 
$$log(\frac{R_L}{R_L + R_{ON}})$$

Logic "0" Input Current (I<sub>INL</sub>) — The current flowing into a digital input when a specified low-level voltage is applied to that input.

Logic "0" Input Voltage Level (V<sub>INL</sub>) — The maximum (or most-positive) digital low-level input voltage for which proper operation of the device is guaranteed.

Logic "1" Input Voltage Level (V<sub>INH</sub>) — The minimum (or least-positive) digital high-level input voltage for which proper operation of the device is guaranteed.

Negative Voltage Supply (V-) — The most negative voltage supply with respect to ground.

Positive Voltage Supply (V+) — The most positive voltage supply with respect to ground.



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**OFF Isolation (ISO<sub>(OFF)</sub>)** — The proportionate amount of a high-frequency analog input signal which is coupled through the channel of an OFF device. This feedthrough is transmitted through C<sub>DS(OFF)</sub> to a load comprised of C<sub>D(OFF)</sub> in parallel with an external load. Isolation generally decreases by 6dB/octave with increasing frequency.

ON Resistance (Ron) — The series ON - channel resistance measured between "S" input and "D" output terminals under specified conditions.

ON Resistance Match (Ron Match) — The channel-to-channel matching of ON resistance when channels are operated under identical conditions.

$$R_{ON} Match = \frac{R_i - R_{AVG}}{R_{AVG}} \times 100\%$$

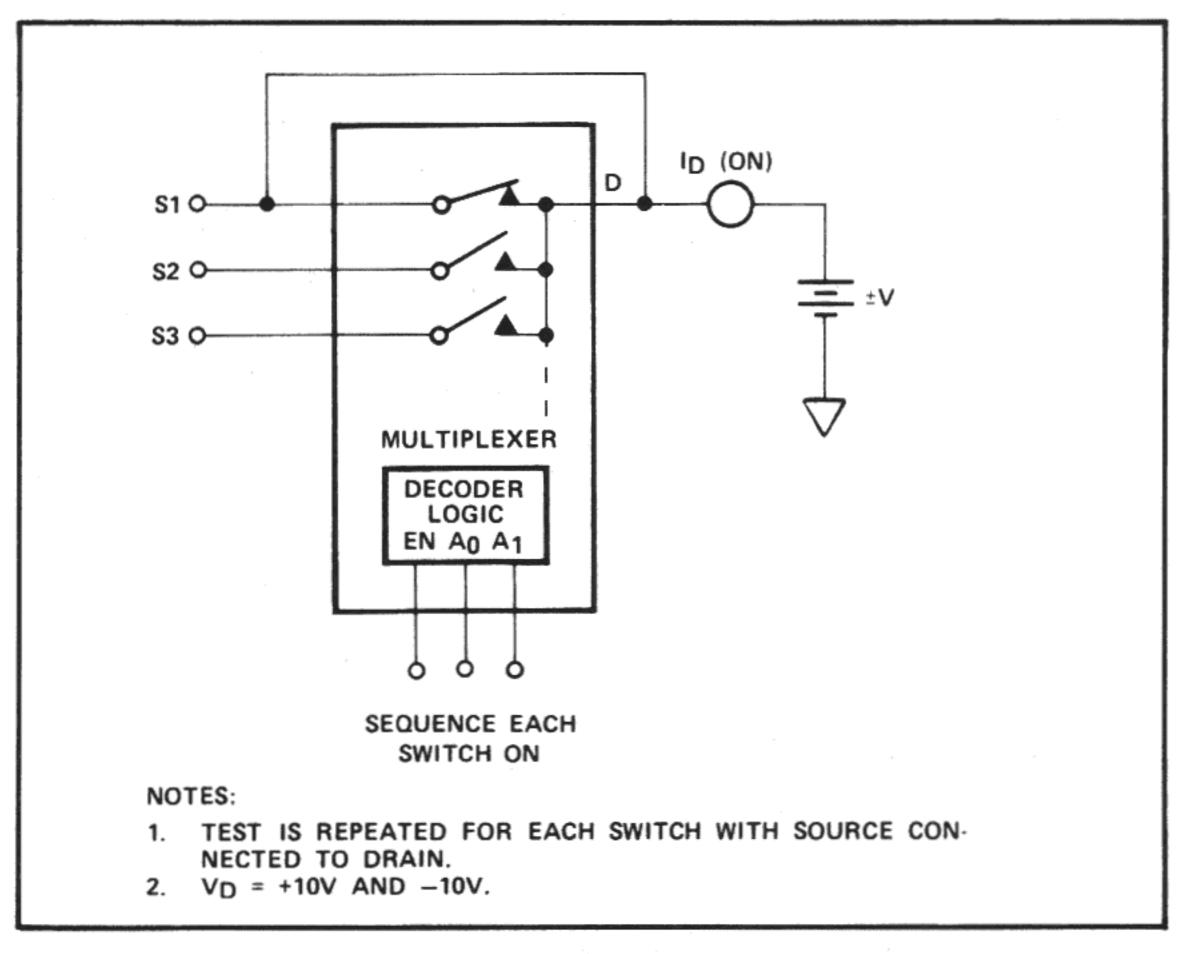
where

N = # of channels in package (i.e., for MUX-08 N = 8, for MUX-16 N = 16, etc.)

R<sub>i</sub> = Each channel's ON resistance

$$R_{AVG} = \frac{1}{N} \sum_{i=1}^{N} R_i$$

# I<sub>(ON)</sub> Test Condition Definitions



ON Resistance Variation ( $\Delta R_{ON}$ ) — The variation of ON resistance produced by the specified analog input voltage change with a constant load current.

$$\Delta R_{ON}$$
 (%) =  $R_{ON}$  @  $V_{A} = -10V - R_{ON}$  @  $V_{A} = +10V$   $\times$  100% Ron @  $V_{A} = 0V$ 

ON Channel Analog Leakage Current (ID(ON) + Is(ON))
Current loss (or gain) through an ON-channel resistance creating a voltage offset across the device. As the direction of current flow is not predictable, only the magnitude is specified at various temperature ranges.

Output Enable Delay Time OFF (toff(EN)) — Multiplexers — The time required to disconnect the analog output from the analog input determined by the digital address input code. It is measured from the 50% point of ENABLE input logic change to the time the output reaches 10% of the initial value.

Output Enable Delay Time ON (ton(EN)) — Mutiplexers — The time required to connect the analog output to the analog input determined by the digital address input code. It is measured from the 50% point of the ENABLE input logic change to the time the output is within 90% of final value.

Output ON Switching Time (ton) — The time required to connect the analog output to the analog input. The time is measured from the 50% point of the logic input change to the time the output reaches 90% of the final value.

Output OFF Switching Time (toff) — The time required to disconnect the analog output from the analog input. The time is measured from the 50% point of the logic input change to the time the output reaches 10% of the initial value.

Output Settling Time (t<sub>s</sub>) — The elapsed time for the analog output to reach its final value within a specified error band after the corresponding digital input code has been changed. It is measured from the 50% point of the logic input change to the time the output reaches final value within specified error band.



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**Power Supply Rejection (PSRR)** — The ratio of the change in switch contact voltage  $(V_D)$  to the change in voltage supply (V+ or V-) that causes it.

+PSRR (dB) = 20 log 
$$\left(\frac{\Delta V_D}{\Delta V+}\right)$$

-PSRR (dB) = 20 log 
$$\left(\frac{\Delta V_D}{\Delta V_-}\right)$$

Switching Time (t<sub>TRAN</sub>) — Multiplexers — The time required to switch and slew from one

analog input channel to another analog input with a full-scale differential between inputs with a high impedance output load. The time is measured from the 50% point of the logic input change to the time the output reaches 80% of the final value.

Total Harmonic Distortion (THD) — The ratio of the signal power at the fundamental frequency to the signal power of all harmonics observed at the switch output  $(V_D)$  with a pure sinusoid applied to the switch input  $(V_S)$ .

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# ANALOG SWITCHES/MULTIPLEXERS SELECTION GUIDE

# **One Channel SPST**

R <sub>ON</sub> Max		Switching Time (µs)		Logic Input for ON	Logic	Levels	Supply Current (mA)	
Product	(Ω)	ton	toff	Switch	VINL	VINH	1+	1—
SW01	100	0.4	0.3	0	0.8	2.0	8.0	4.5
SW02	100	0.4	0.3	1	0.8	2.0	8.0	4.5

### 2-Channel SPST

	R <sub>on</sub> Max	Switching Time (µs)		Logic Input for ON	Logic	Levels	Supply Current (mA)	
Product	(Ω)	ton	toff	Switch	VINL	VINH	1+	<b> </b> -
SSM2402	85	10000	4000	1	0.8	2.0	7.5	6.0
SSM2412	85	3500	1500	1	0.8	2.0	7.5	6.0

# 4-Channel SPST

	0.0		ching e (μs)	Logic Input for ON	Logic Levels		Supply Current (mA)	
Product	$(\Omega)$	ton	toff	Switch	VINL	VINH	1+	.  -
SW06	80	0.5	0.4	Note	0.8	2.0	6.0	5.0
SW201	80	0.5	0.4	0	0.8	2.0	9.0	5.0
SW202	80	0.5	0.4	1	0.8	2.0	9.0	5.0
SW7510	75	0.45	0.3	Note	0.8	2.0	9.0	5.0
SW7511	75	0.45	0.3	Note	0.8	2.0	9.0	5.0

NOTE: See individual data sheet for more details.

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# 8-Channel MUX

	R <sub>ON</sub> Max	Transition Time	Logic	Supply Current (mA)		
Product	(Ω)	(μs)	VINL	VINH	1+	<u> </u>
MUX08	300	2.1	0.7	2.0	12.0	3.8
MUX88	400	2.1	0.8	2.0	15.0	5.0

# **Dual 4-Channel MUX**

Product	R <sub>ON</sub> Max (Ω)	Transition Time (μs)	Logic	Supply Current (mA)		
			VINL	VINH	1+	1—
MUX24	300	2.1	0.7	2.0	12.0	3.8

# 16-Channel MUX

Product	R <sub>ON</sub> Max (Ω)	Transition Time (μs)	Logic Levels		Supply Current (mA)	
			VINL	VINH	1+	1—
MUX16	380	2.0	0.7	2.0	19.0	7.0

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# **Dual 8-Channel MUX**

	Ron	Transition Time	Logic Levels		Supply Current (mA)	
Product	(Ω)	(μs)	VINL	VINH	1+	`  -
MUX28	380	2.0	0.7	2.0	19.0	7.0